Freescale
Data Sheet: Technical Data

Document Number: MPC5567
Rev. 2, December 2012

MPC5567 Microcontroller Data Sheet

This document provides electrical specifications, pin assignments, and package diagrams for the MPC5567 microcontroller device. For functional characteristics, refer to the *MPC5567 Microcontroller Reference Manual*.

1 Overview

The MPC5567 microcontroller (MCU) is a member of the MPC5500 family of microcontrollers built on the Power Architecture® embedded technology. This family of parts has many new features coupled with high performance CMOS technology to provide substantial reduction of cost per feature and significant performance improvement over the MPC500 family.

The host processor core of this device complies with the Power Architecture embedded category that is 100% user-mode compatible (including floating point library) with the original PowerPC instruction set.The embedded architecture enhancements improve the performance in embedded applications. The core also has additional instructions, including digital signal processing (DSP) instructions, beyond the original PowerPC instruction set.

Contents

1 Overview 1
2 Ordering Information 3
3 Electrical Characteristics 3
3.1 Maximum Ratings 3
3.2 Thermal Characteristics. 5
3.3 Package 8
3.4 EMI (Electromagnetic Interference) Characteristics 8
3.5 ESD (Electromagnetic Static Discharge) Characteristics9
3.6 Voltage Regulator Controller (VRC) and Power-On Reset (POR) Electrical Specifications9
3.7 Power-Up/Down Sequencing 10
3.8 DC Electrical Specifications. 14
3.9 Oscillator and FMPLL Electrical Characteristics . . 20
3.10 eQADC Electrical Characteristics 22
3.11 H7Fa Flash Memory Electrical Characteristics . . . 23
3.12 AC Specifications 24
3.13 AC Timing 26
3.14 Fast Ethernet AC Timing Specifications 46
4 Mechanicals. 50
4.1 MPC5567 324 PBGA Pinouts 50
4.2 MPC5567 416 PBGA Pinout 50
4.3 MPC5567 324-Pin Package Dimensions 54
4.4 MPC5567 416-Pin Package Dimensions 56
5 Revision History for the MPC5567 Data Sheet 58
5.1 Information Changed Between Revisions 1.0 and 2.0 58
5.2 Information Changed Between Rev. 0.0 and 1.0. . 58

© Freescale Inc., 2007,2012. All rights reserved.

The MPC5500 family of parts contains many new features coupled with high performance CMOS technology to provide significant performance improvement over the MPC565x.

The host processor core of the MPC5567 also includes an instruction set enhancement allowing variable length encoding (VLE). This allows optional encoding of mixed 16- and 32-bit instructions. With this enhancement, it is possible to significantly reduce the code size footprint.

The MPC5567 has two levels of memory hierarchy. The fastest accesses are to the 8-kilobytes (KB) unified cache. The next level in the hierarchy contains the 80-KB on-chip internal SRAM and two-megabytes (MB) internal flash memory. The internal SRAM and flash memory hold instructions and data. The external bus interface is designed to support most of the standard memories used with the MPC5*xx* family.

The complex input/output timer functions of the MPC5567 are performed by an enhanced time processor unit (eTPU) engine. The eTPU engine controls 32 hardware channels. The eTPU has been enhanced over the TPU by providing: 24-bit timers, double-action hardware channels, variable number of parameters per channel, angle clock hardware, and additional control and arithmetic instructions. The eTPU is programmed using a high-level programming language.

The less complex timer functions of the MPC5567 are performed by the enhanced modular input/output system (eMIOS). The eMIOS' 24 hardware channels are capable of single-action, double-action, pulse-width modulation (PWM), and modulus-counter operations. Motor control capabilities include edge-aligned and center-aligned PWM.

Off-chip communication is performed by a suite of serial protocols including controller area networks (FlexCANs), enhanced deserial/serial peripheral interfaces (DSPIs), and enhanced serial communications interfaces (eSCIs). The DSPIs support pin reduction through hardware serialization and deserialization of timer channels and general-purpose input/output (GPIOs) signals.

The MCU has an on-chip enhanced queued dual analog-to-digital converter (eQADC).and package sve40-channels.

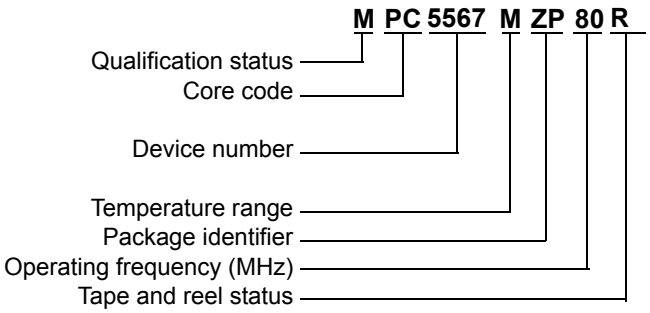
The system integration unit (SIU) performs several chip-wide configuration functions. Pad configuration and general-purpose input and output (GPIO) are controlled from the SIU. External interrupts and reset control are also determined by the SIU. The internal multiplexer submodule provides multiplexing of eQADC trigger sources, daisy chaining the DSPIs, and external interrupt signal multiplexing.

The Fast Ethernet (FEC) module is a RISC-based controller that supports both 10 and 100 Mbps Ethernet/IEEE® 802.3 networks and is compatible with three different standard MAC (media access controller) PHY (physical) interfaces to connect to an external Ethernet bus. The FEC supports the 10 or 100 Mbps MII (media independent interface), and the 10 Mbps-only with a seven-wire interface, which uses a subset of the MII signals. The upper 16-bits of the 32-bit external bus interface (EBI) are used to connect to an external Ethernet device. The FEC contains built-in transmit and receive message FIFOs and DMA support.

The FlexRay controller provides functional node networking, with static and dynamic host access, to develop highly dependable automotive control systems that require the full implementation of the FlexRay protocol, as published in *FlexRay Protocol Specification 2.0*. The FlexRay module uses fault-tolerant, time-triggered events and clock synchronization mechanisms to maintain the global time of the functional

nodes. Bus guardian operations are available for each channel in a multi- or redundant-channel configuration.

2 Ordering Information



Temperature Range
M = –40° C to 125° C

Package Identifier
ZP = 416PBGA SnPb
VR = 416PBGA Pb-free
ZQ = 324PBGA SnPb
VZ = 324PBGA Pb-free

Operating Frequency
80 = 80 MHz
112 = 112 MHz
132 = 132 MHz

Tape and Reel Status
R = Tape and reel
(blank) = Trays

Qualification Status
P = Pre qualification
M = Fully spec. qualified, general market flow
S = Fully spec. qualified, automotive flow

Note: Not all options are available on all devices. Refer to Table 1.

Figure 1. MPC5500 Family Part Number Example

Unless noted in this data sheet, all specifications apply from T_L to T_H.

Table 1. Orderable Part Numbers

Freescale Part Number[1]	Package Description	Speed (MHz)		Operating Temperature [2]	
		Nominal	Max. [3] (f_{MAX})	Min. (T_L)	Max. (T_H)
MPC5567MVR132	MPC5567 416 package Lead-free (PbFree)	132	135	–40° C	125° C
MPC5567MVR112		112	114		
MPC5567MVR80		80	82		
MPC5567MVZ132	MPC5567 324 package Lead-free (PbFree)	132	135	–40° C	125° C
MPC5567MVZ80		80	82		
MPC5567MVZ112		112	114		
MPC5567MZP132	MPC5567 416 package Leaded (SnPb)	132	135	–40° C	125° C
MPC5567MZP112		112	114		
MPC5567MZP80		80	82		
MPC5567MZQ132	MPC5567 324 package Leaded (SnPb)	132	135	–40° C	125° C
MPC5567MZQ112		112	114		
MPC5567MZQ80		80	82		

[1] All devices are PPC5567, rather than MPC5567 or SPC5567, until product qualifications are complete. Not all configurations are available in the PPC parts.

[2] The lowest ambient operating temperature is referenced by T_L; the highest ambient operating temperature is referenced by T_H.

[3] Speed is the nominal maximum frequency. Max. speed is the maximum speed allowed including frequency modulation (FM). 82 MHz parts allow for 80 MHz system clock + 2% FM; 114 MHz parts allow for 112 MHz system clock + 2% FM; and 135 MHz parts allow for 132 MHz system clock + 2% FM.

3 Electrical Characteristics

This section contains detailed information on power considerations, DC/AC electrical characteristics, and AC timing specifications for the MCU.

3.1 Maximum Ratings

Table 2. Absolute Maximum Ratings [1]

Spec	Characteristic	Symbol	Min.	Max.	Unit
1	1.5 V core supply voltage [2]	V_{DD}	–0.3	1.7	V
2	Flash program/erase voltage	V_{PP}	–0.3	6.5	V
4	Flash read voltage	V_{FLASH}	–0.3	4.6	V
5	SRAM standby voltage	V_{STBY}	–0.3	1.7	V
6	Clock synthesizer voltage	V_{DDSYN}	–0.3	4.6	V
7	3.3 V I/O buffer voltage	V_{DD33}	–0.3	4.6	V
8	Voltage regulator control input voltage	V_{RC33}	–0.3	4.6	V
9	Analog supply voltage (reference to V_{SSA})	V_{DDA}	–0.3	5.5	V
10	I/O supply voltage (fast I/O pads) [3]	V_{DDE}	–0.3	4.6	V
11	I/O supply voltage (slow and medium I/O pads) [3]	V_{DDEH}	–0.3	6.5	V
12	DC input voltage [4] V_{DDEH} powered I/O pads V_{DDE} powered I/O pads	V_{IN}	 –1.0 [5] –1.0 [5]	 6.5 [6] 4.6 [7]	V
13	Analog reference high voltage (reference to V_{RL})	V_{RH}	–0.3	5.5	V
14	V_{SS} to V_{SSA} differential voltage	$V_{SS} – V_{SSA}$	–0.1	0.1	V
15	V_{DD} to V_{DDA} differential voltage	$V_{DD} – V_{DDA}$	$–V_{DDA}$	V_{DD}	V
16	V_{REF} differential voltage	$V_{RH} – V_{RL}$	–0.3	5.5	V
17	V_{RH} to V_{DDA} differential voltage	$V_{RH} – V_{DDA}$	–5.5	5.5	V
18	V_{RL} to V_{SSA} differential voltage	$V_{RL} – V_{SSA}$	–0.3	0.3	V
19	V_{DDEH} to V_{DDA} differential voltage	$V_{DDEH} – V_{DDA}$	$–V_{DDA}$	V_{DDEH}	V
20	V_{DDF} to V_{DD} differential voltage	$V_{DDF} – V_{DD}$	–0.3	0.3	V
21	V_{RC33} to V_{DDSYN} differential voltage spec has been moved to Table 9 DC Electrical Specifications, Spec 43a.				
22	V_{SSSYN} to V_{SS} differential voltage	$V_{SSSYN} – V_{SS}$	–0.1	0.1	V
23	V_{RCVSS} to V_{SS} differential voltage	$V_{RCVSS} – V_{SS}$	–0.1	0.1	V
24	Maximum DC digital input current [8] (per pin, applies to all digital pins) [4]	I_{MAXD}	–2	2	mA
25	Maximum DC analog input current [9] (per pin, applies to all analog pins)	I_{MAXA}	–3	3	mA

Table 2. Absolute Maximum Ratings [1] (continued)

Spec	Characteristic	Symbol	Min.	Max.	Unit
26	Maximum operating temperature range [10] Die junction temperature	T_J	T_L	150.0	°C
27	Storage temperature range	T_{STG}	–55.0	150.0	°C
28	Maximum solder temperature [11] Lead free (Pb-free) Leaded (SnPb)	T_{SDR}	— —	260.0 245.0	°C
29	Moisture sensitivity level [12]	MSL	—	3	

1 Functional operating conditions are given in the DC electrical specifications. Absolute maximum ratings are stress ratings only, and functional operation at the maxima is not guaranteed. Stress beyond any of the listed maxima can affect device reliability or cause permanent damage to the device.

2 1.5 V ± 10% for proper operation. This parameter is specified at a maximum junction temperature of 150 °C.

3 All functional non-supply I/O pins are clamped to V_{SS} and V_{DDE}, or V_{DDEH}.

4 AC signal overshoot and undershoot of up to ± 2.0 V of the input voltages is permitted for an accumulative duration of 60 hours over the complete lifetime of the device (injection current not limited for this duration).

5 Internal structures hold the voltage greater than –1.0 V if the injection current limit of 2 mA is met. Keep the negative DC voltage greater than –0.6 V on SINB during the internal power-on reset (POR) state.

6 Internal structures hold the input voltage less than the maximum voltage on all pads powered by V_{DDEH} supplies, if the maximum injection current specification is met (2 mA for all pins) and V_{DDEH} is within the operating voltage specifications.

7 Internal structures hold the input voltage less than the maximum voltage on all pads powered by V_{DDE} supplies, if the maximum injection current specification is met (2 mA for all pins) and V_{DDE} is within the operating voltage specifications.

8 Total injection current for all pins (including both digital and analog) must not exceed 25 mA.

9 Total injection current for all analog input pins must not exceed 15 mA.

10 Lifetime operation at these specification limits is not guaranteed.

11 Moisture sensitivity profile per IPC/JEDEC J-STD-020D.

12 Moisture sensitivity per JEDEC test method A112.

3.2 Thermal Characteristics

The shaded rows in the following table indicate information specific to a four-layer board.

Table 3. MPC5567 Thermal Characteristics

Spec	MPC5567 Thermal Characteristic	Symbol	Packages		Unit
			324 PBGA	416 PBGA	
1	Junction to ambient [1, 2], natural convection (one-layer board)	$R_{\theta JA}$	29	25	°C/W
2	Junction to ambient [1, 3], natural convection (four-layer board 2s2p)	$R_{\theta JA}$	19	17	°C/W
3	Junction to ambient (@200 ft./min., one-layer board)	$R_{\theta JMA}$	23	19	°C/W
4	Junction to ambient (@200 ft./min., four-layer board 2s2p)	$R_{\theta JMA}$	16	14	°C/W
5	Junction to board [4] (four-layer board 2s2p)	$R_{\theta JB}$	10	9	°C/W
6	Junction to case [5]	$R_{\theta JC}$	7	7	°C/W
7	Junction to package top [6], natural convection	Ψ_{JT}	2	2	°C/W

1 Junction temperature is a function of on-chip power dissipation, package thermal resistance, mounting site (board) temperature, ambient temperature, air flow, power dissipation of other components on the board, and board thermal resistance.

2 Per SEMI G38-87 and JEDEC JESD51-2 with the single-layer board horizontal.

3 Per JEDEC JESD51-6 with the board horizontal.

4 Thermal resistance between the die and the printed circuit board per JEDEC JESD51-8. Board temperature is measured on the top surface of the board near the package.

5 Indicates the average thermal resistance between the die and the case top surface as measured by the cold plate method (MIL SPEC-883 Method 1012.1) with the cold plate temperature used for the case temperature.

6 Thermal characterization parameter indicating the temperature difference between package top and the junction temperature per JEDEC JESD51-2.

3.2.1 General Notes for Specifications at Maximum Junction Temperature

An estimation of the device junction temperature, T_J, can be obtained from the equation:

$$T_J = T_A + (R_{\theta JA} \times P_D)$$

where:

T_A = ambient temperature for the package (^oC)

$R_{\theta JA}$ = junction to ambient thermal resistance ($^oC/W$)

P_D = power dissipation in the package (W)

The thermal resistance values used are based on the JEDEC JESD51 series of standards to provide consistent values for estimations and comparisons. The difference between the values determined for the single-layer (1s) board compared to a four-layer board that has two signal layers, a power and a ground plane (2s2p), demonstrate that the effective thermal resistance is not a constant. The thermal resistance depends on the:

- Construction of the application board (number of planes)
- Effective size of the board which cools the component
- Quality of the thermal and electrical connections to the planes
- Power dissipated by adjacent components

Connect all the ground and power balls to the respective planes with one via per ball. Using fewer vias to connect the package to the planes reduces the thermal performance. Thinner planes also reduce the thermal performance. When the clearance between the vias leave the planes virtually disconnected, the thermal performance is also greatly reduced.

As a general rule, the value obtained on a single-layer board is within the normal range for the tightly packed printed circuit board. The value obtained on a board with the internal planes is usually within the normal range if the application board has:

- One oz. (35 micron nominal thickness) internal planes
- Components are well separated
- Overall power dissipation on the board is less than 0.02 W/cm^2

The thermal performance of any component depends on the power dissipation of the surrounding components. In addition, the ambient temperature varies widely within the application. For many natural convection and especially closed box applications, the board temperature at the perimeter (edge) of the package is approximately the same as the local air temperature near the device. Specifying the local ambient conditions explicitly as the board temperature provides a more precise description of the local ambient conditions that determine the temperature of the device.

At a known board temperature, the junction temperature is estimated using the following equation:

$$T_J = T_B + (R_{\theta JB} \times P_D)$$

where:

T_J = junction temperature (^oC)

T_B = board temperature at the package perimeter ($^oC/W$)

$R_{\theta JB}$ = junction-to-board thermal resistance ($^oC/W$) per JESD51-8

P_D = power dissipation in the package (W)

When the heat loss from the package case to the air does not factor into the calculation, an acceptable value for the junction temperature is predictable. Ensure the application board is similar to the thermal test condition, with the component soldered to a board with internal planes.

The thermal resistance is expressed as the sum of a junction-to-case thermal resistance plus a case-to-ambient thermal resistance:

$$R_{\theta JA} = R_{\theta JC} + R_{\theta CA}$$

where:

$R_{\theta JA}$ = junction-to-ambient thermal resistance ($^oC/W$)

$R_{\theta JC}$ = junction-to-case thermal resistance ($^oC/W$)

$R_{\theta CA}$ = case-to-ambient thermal resistance ($^oC/W$)

$R_{\theta JC}$ is device related and is not affected by other factors. The thermal environment can be controlled to change the case-to-ambient thermal resistance, $R_{\theta CA}$. For example, change the air flow around the device, add a heat sink, change the mounting arrangement on the printed circuit board, or change the thermal dissipation on the printed circuit board surrounding the device. This description is most useful for packages with heat sinks where 90% of the heat flow is through the case to heat sink to ambient. For most packages, a better model is required.

A more accurate two-resistor thermal model can be constructed from the junction-to-board thermal resistance and the junction-to-case thermal resistance. The junction-to-case thermal resistance describes when using a heat sink or where a substantial amount of heat is dissipated from the top of the package. The junction-to-board thermal resistance describes the thermal performance when most of the heat is conducted to the printed circuit board. This model can be used to generate simple estimations and for computational fluid dynamics (CFD) thermal models.

To determine the junction temperature of the device in the application on a prototype board, use the thermal characterization parameter (Ψ_{JT}) to determine the junction temperature by measuring the temperature at the top center of the package case using the following equation:

$$T_J = T_T + (\Psi_{JT} \times P_D)$$

where:

T_T = thermocouple temperature on top of the package (^oC)

Ψ_{JT} = thermal characterization parameter ($^oC/W$)

P_D = power dissipation in the package (W)

The thermal characterization parameter is measured in compliance with the JESD51-2 specification using a 40-gauge type T thermocouple epoxied to the top center of the package case. Position the thermocouple so that the thermocouple junction rests on the package. Place a small amount of epoxy on the thermocouple junction and approximately 1 mm of wire extending from the junction. Place the thermocouple wire flat against the package case to avoid measurement errors caused by the cooling effects of the thermocouple wire.

References:

Semiconductor Equipment and Materials International
3081 Zanker Rd.
San Jose, CA., 95134
(408) 943-6900

MIL-SPEC and EIA/JESD (JEDEC) specifications are available from Global Engineering Documents at 800-854-7179 or 303-397-7956.

JEDEC specifications are available on the web at http://www.jedec.org.

1. C.E. Triplett and B. Joiner, “An Experimental Characterization of a 272 PBGA Within an Automotive Engine Controller Module,” Proceedings of SemiTherm, San Diego, 1998, pp. 47–54.
2. G. Kromann, S. Shidore, and S. Addison, “Thermal Modeling of a PBGA for Air-Cooled Applications,” Electronic Packaging and Production, pp. 53–58, March 1998.
3. B. Joiner and V. Adams, “Measurement and Simulation of Junction to Board Thermal Resistance and Its Application in Thermal Modeling,” Proceedings of SemiTherm, San Diego, 1999, pp. 212–220.

3.3 Package

The MPC5567 is available in packaged form. Read the package options in Section 2, “Ordering Information.” Refer to Section 4, “Mechanicals,” for pinouts and package drawings.

3.4 EMI (Electromagnetic Interference) Characteristics

Table 4. EMI Testing Specifications [1]

Spec	Characteristic	Minimum	Typical	Maximum	Unit
1	Scan range	0.15	—	1000	MHz
2	Operating frequency	—	—	f_{MAX}	MHz
3	V_{DD} operating voltages	—	1.5	—	V
4	V_{DDSYN}, V_{RC33}, V_{DD33}, V_{FLASH}, V_{DDE} operating voltages	—	3.3	—	V
5	V_{PP}, V_{DDEH}, V_{DDA} operating voltages	—	5.0	—	V
6	Maximum amplitude	—	—	14 [2] 32 [3]	dBuV
7	Operating temperature	—	—	25	°C

1 EMI testing and I/O port waveforms per SAE J1752/3 issued 1995-03. Qualification testing was performed on the MPC5554 and applied to the MPC5500 family as generic EMI performance data.

2 Measured with the single-chip EMI program.

3 Measured with the expanded EMI program.

3.5 ESD (Electromagnetic Static Discharge) Characteristics

Table 5. ESD Ratings [1, 2]

Characteristic	Symbol	Value	Unit
ESD for human body model (HBM)		2000	V
HBM circuit description	R1	1500	Ω
	C	100	pF
ESD for field induced charge model (FDCM)		500 (all pins) 750 (corner pins)	V
Number of pulses per pin: Positive pulses (HBM) Negative pulses (HBM)	 — —	 1 1	 — —
Interval of pulses	—	1	second

1 All ESD testing conforms to CDF-AEC-Q100 Stress Test Qualification for Automotive Grade Integrated Circuits.

2 Device failure is defined as: 'If after exposure to ESD pulses, the device does not meet the device specification requirements, which includes the complete DC parametric and functional testing at room temperature and hot temperature.

3.6 Voltage Regulator Controller (V_{RC}) and Power-On Reset (POR) Electrical Specifications

The following table lists the V_{RC} and POR electrical specifications:

Table 6. V_{RC} and POR Electrical Specifications

Spec	Characteristic		Symbol	Min.	Max.	Units
1	1.5 V (V_{DD}) POR [1]	Negated (ramp up) Asserted (ramp down)	V_{POR15}	1.1 1.1	1.35 1.35	V
2	3.3 V (V_{DDSYN}) POR [1]	Asserted (ramp up) Negated (ramp up) Asserted (ramp down) Negated (ramp down)	V_{POR33}	0.0 2.0 2.0 0.0	0.30 2.85 2.85 0.30	V
3	$\overline{\text{RESET}}$ pin supply (V_{DDEH6}) POR [1, 2]	Negated (ramp up) Asserted (ramp down)	V_{POR5}	2.0 2.0	2.85 2.85	V
4	V_{RC33} voltage	Before V_{RC} allows the pass transistor to start turning on	V_{TRANS_START}	1.0	2.0	V
5		When V_{RC} allows the pass transistor to completely turn on [3, 4]	V_{TRANS_ON}	2.0	2.85	V
6		When the voltage is greater than the voltage at which the V_{RC} keeps the 1.5 V supply in regulation [5, 6]	$V_{VRC33REG}$	3.0	—	V
7	Current can be sourced by V_{RCCTL} at Tj:	–40° C 25° C 150° C	I_{VRCCTL} [7]	11.0 9.0 7.5	— — —	mA mA mA
8	Voltage differential during power up such that: V_{DD33} can lag V_{DDSYN} or V_{DDEH6} before V_{DDSYN} and V_{DDEH6} reach the V_{POR33} and V_{POR5} minimums respectively.		V_{DD33_LAG}	—	1.0	V

Table 6. V_{RC} and POR Electrical Specifications (continued)

Spec	Characteristic		Symbol	Min.	Max.	Units
9	Absolute value of slew rate on power supply pins		—	—	50	V/ms
10	Required gain at Tj: $I_{DD} \div I_{VRCCTL}$ (@ $f_{sys} = f_{MAX}$) 6, 7, 8, 9	– 40° C 25° C 150° C	BETA[10]	40 45 55	— — 500	— — —

1 The internal POR signals are V_{POR15}, V_{POR33}, and V_{POR5}. On power up, assert $\overline{\text{RESET}}$ before the internal POR negates. $\overline{\text{RESET}}$ must remain asserted until the power supplies are within the operating conditions as specified in Table 9 DC Electrical Specifications. On power down, assert $\overline{\text{RESET}}$ before any power supplies fall outside the operating conditions and until the internal POR asserts.

2 V_{IL_S} (Table 9, Spec15) is guaranteed to scale with V_{DDEH6} down to V_{POR5}.

3 Supply full operating current for the 1.5 V supply when the 3.3 V supply reaches this range.

4 It is possible to reach the current limit during ramp up—do not treat this event as short circuit current.

5 At peak current for device.

6 Requires compliance with Freescale's recommended board requirements and transistor recommendations. Board signal traces/routing from the V_{RCCTL} package signal to the base of the external pass transistor and between the emitter of the pass transistor to the V_{DD} package signals must have a maximum of 100 nH inductance and minimal resistance (less than 1 Ω). V_{RCCTL} must have a nominal 1 µF phase compensation capacitor to ground. V_{DD} must have a 20 µF (nominal) bulk capacitor (greater than 4 µF over all conditions, including lifetime). Place high-frequency bypass capacitors consisting of eight 0.01 µF, two 0.1 µF, and one 1 µF capacitors around the package on the V_{DD} supply signals.

7 I_{VRCCTL} is measured at the following conditions: V_{DD} = 1.35 V, V_{RC33} = 3.1 V, V_{VRCCTL} = 2.2 V.

8 Refer to Table 1 for the maximum operating frequency.

9 Values are based on I_{DD} from high-use applications as explained in the I_{DD} Electrical Specification.

10 Represents the worst-case external transistor BETA. It is measured on a per-part basis and calculated as ($I_{DD} \div I_{VRCCTL}$).

3.7 Power-Up/Down Sequencing

Power sequencing between the 1.5 V power supply and V_{DDSYN} or the $\overline{\text{RESET}}$ power supplies is required if using an external 1.5 V power supply with V_{RC33} tied to ground (GND). To avoid power-sequencing, V_{RC33} must be powered up within the specified operating range, even if the on-chip voltage regulator controller is not used. Refer to Section 3.7.2, "Power-Up Sequence (VRC33 Grounded)," and Section 3.7.3, "Power-Down Sequence (VRC33 Grounded)."

Power sequencing requires that V_{DD33} must reach a certain voltage where the values are read as ones before the POR signal negates. Refer to Section 3.7.1, "Input Value of Pins During POR Dependent on VDD33."

Although power sequencing is not required between V_{RC33} and V_{DDSYN} during power up, V_{RC33} must not lead V_{DDSYN} by more than 600 mV or lag by more than 100 mV for the V_{RC} stage turn-on to operate within specification. Higher spikes in the emitter current of the pass transistor occur if V_{RC33} leads or lags V_{DDSYN} by more than these amounts. The value of that higher spike in current depends on the board power supply circuitry and the amount of board level capacitance.

Furthermore, when all of the PORs negate, the system clock starts to toggle, adding another large increase of the current consumed by V_{RC33}. If V_{RC33} lags V_{DDSYN} by more than 100 mV, the increase in current consumed can drop V_{DD} low enough to assert the 1.5 V POR again. Oscillations are possible when the 1.5 V POR asserts and stops the system clock, causing the voltage on V_{DD} to rise until the 1.5 V POR negates again. All oscillations stop when V_{RC33} is powered sufficiently.

When powering down, V_{RC33} and V_{DDSYN} have no delta requirement to each other, because the bypass capacitors internal and external to the device are already charged. When not powering up or down, no delta between V_{RC33} and V_{DDSYN} is required for the V_{RC} to operate within specification.

There are no power up/down sequencing requirements to prevent issues such as latch-up, excessive current spikes, and so on. Therefore, the state of the I/O pins during power up and power down varies depending on which supplies are powered.

Table 7 gives the pin state for the sequence cases for all pins with pad type pad_fc (fast type).

Table 7. Pin Status for Fast Pads During the Power Sequence

V_{DDE}	V_{DD33}	V_{DD}	POR	Pin Status for Fast Pad Output Driver pad_fc (fast)
Low	—	—	Asserted	Low
V_{DDE}	Low	Low	Asserted	High
V_{DDE}	Low	V_{DD}	Asserted	High
V_{DDE}	V_{DD33}	Low	Asserted	High impedance (Hi-Z)
V_{DDE}	V_{DD33}	V_{DD}	Asserted	Hi-Z
V_{DDE}	V_{DD33}	V_{DD}	Negated	Functional

Table 8 gives the pin state for the sequence cases for all pins with pad type pad_mh (medium type) and pad_sh (slow type).

Table 8. Pin Status for Medium and Slow Pads During the Power Sequence

V_{DDEH}	V_{DD}	POR	Pin Status for Medium and Slow Pad Output Driver pad_mh (medium) pad_sh (slow)
Low	—	Asserted	Low
V_{DDEH}	Low	Asserted	High impedance (Hi-Z)
V_{DDEH}	V_{DD}	Asserted	Hi-Z
V_{DDEH}	V_{DD}	Negated	Functional

The values in Table 7 and Table 8 do not include the effect of the weak-pull devices on the output pins during power up.

Before exiting the internal POR state, the voltage on the pins go to a high-impedance state until POR negates. When the internal POR negates, the functional state of the signal during reset applies and the weak-pull devices
(up or down) are enabled as defined in the device reference manual. If V_{DD} is too low to correctly propagate the logic signals, the weak-pull devices can pull the signals to V_{DDE} and V_{DDEH}.

To avoid this condition, minimize the ramp time of the V_{DD} supply to a time period less than the time required to enable the external circuitry connected to the device outputs.

During initial power ramp-up, when V_{stby} is 0.6v or above. a typical current of 1-3mA and maximum of 4mA may be seen until V_{DD} is applied. This current will not reoccur until V_{stby} is lowered below V_{stby} min. specification.

Figure 2 shows an approximate interpolation of the I_{STBY} worst-case specification to estimate values at different voltages and temperatures. The vertical lines shown at 25 °C, 60 °C, and 150 °C in Figure 2 are the actual I_{DD_STBY} specifications (27d) listed in Table 9.

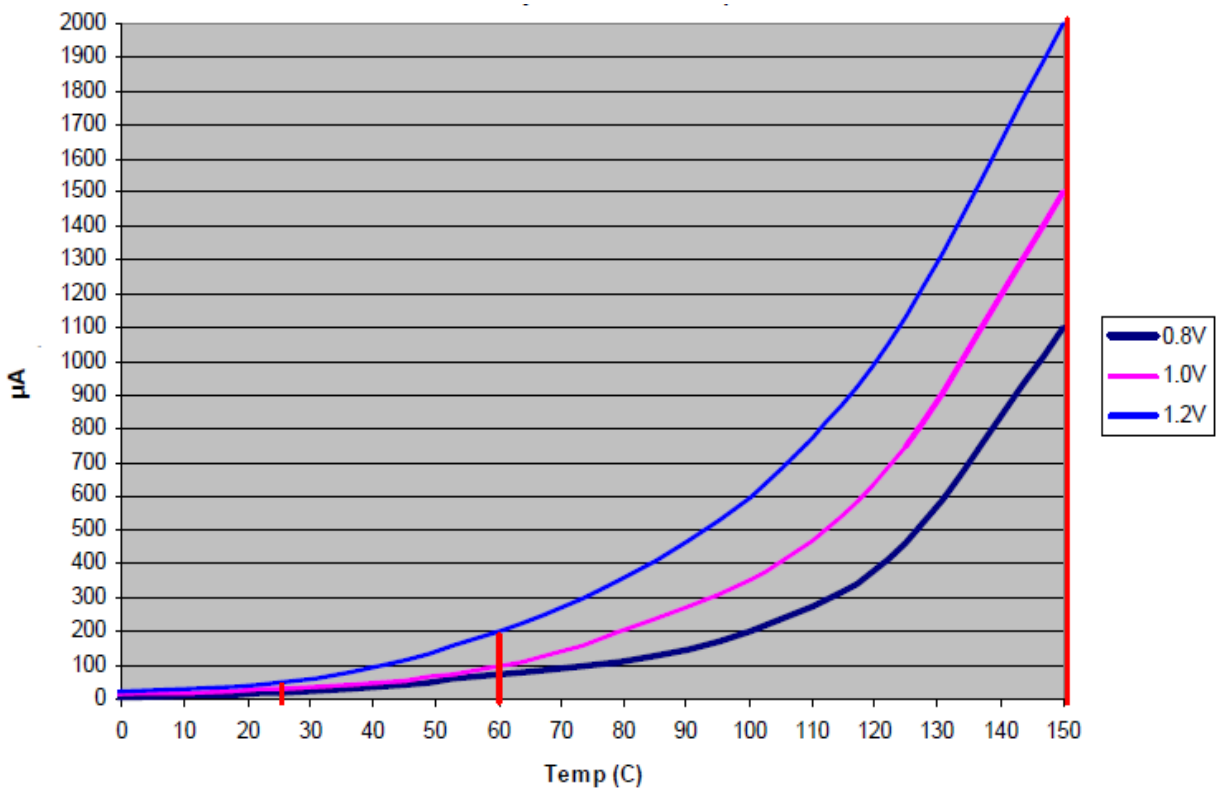


Figure 2. fI_{STBY} Worst-case Specifications

3.7.1 Input Value of Pins During POR Dependent on V_{DD33}

When powering up the device, V_{DD33} must not lag the latest V_{DDSYN} *or* $\overline{\text{RESET}}$ power pin (V_{DDEH6}) by more than the V_{DD33} lag specification listed in Table 6, spec 8. This avoids accidentally selecting the bypass clock mode because the internal versions of PLLCFG[0:1] and $\overline{\text{RSTCFG}}$ are not powered and therefore cannot read the default state when POR negates. V_{DD33} can lag V_{DDSYN} *or* the $\overline{\text{RESET}}$ power pin (V_{DDEH6}), but cannot lag both by more than the V_{DD33} lag specification. This V_{DD33} lag specification applies during power up only. V_{DD33} has no lead or lag requirements when powering down.

3.7.2 Power-Up Sequence (V_{RC33} Grounded)

The 1.5 V V_{DD} power supply must rise to 1.35 V before the 3.3 V V_{DDSYN} power supply and the $\overline{\text{RESET}}$ power supply rises above 2.0 V. This ensures that digital logic in the PLL for the 1.5 V power supply does not begin to operate below the specified operation range lower limit of 1.35 V. Because the internal 1.5 V POR is disabled, the internal 3.3 V POR or the $\overline{\text{RESET}}$ power POR must hold the device in reset. Since they can negate as low as 2.0 V, V_{DD} must be within specification before the 3.3 V POR and the $\overline{\text{RESET}}$ POR negate.

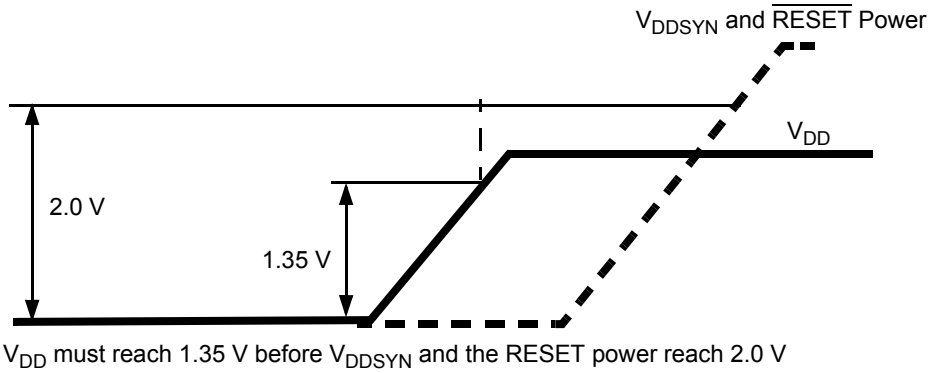


Figure 3. Power-Up Sequence (V_{RC33} Grounded)

3.7.3 Power-Down Sequence (V_{RC33} Grounded)

The only requirement for the power-down sequence with V_{RC33} grounded is if V_{DD} decreases to less than its operating range, V_{DDSYN} or the $\overline{\text{RESET}}$ power must decrease to less than 2.0 V before the V_{DD} power increases to its operating range. This ensures that the digital 1.5 V logic, which is reset only by an ORed POR and can cause the 1.5 V supply to decrease less than its specification value, resets correctly. See Table 6, footnote 1.

3.8 DC Electrical Specifications

Table 9. DC Electrical Specifications ($T_A = T_L$ to T_H)

Spec	Characteristic	Symbol	Min	Max.	Unit
1	Core supply voltage (average DC RMS voltage)	V_{DD}	1.35	1.65	V
2	Input/output supply voltage (fast input/output) [1]	V_{DDE}	1.62	3.6	V
3	Input/output supply voltage (slow and medium input/output)	V_{DDEH}	3.0	5.25	V
4	3.3 V input/output buffer voltage	V_{DD33}	3.0	3.6	V
5	Voltage regulator control input voltage	V_{RC33}	3.0	3.6	V
6	Analog supply voltage [2]	V_{DDA}	4.5	5.25	V
8	Flash programming voltage [3]	V_{PP}	4.5	5.25	V
9	Flash read voltage	V_{FLASH}	3.0	3.6	V
10	SRAM standby voltage [4]	V_{STBY}	0.8	1.2	V
11	Clock synthesizer operating voltage	V_{DDSYN}	3.0	3.6	V
12	Fast I/O input high voltage	V_{IH_F}	$0.65 \times V_{DDE}$	$V_{DDE} + 0.3$	V
13	Fast I/O input low voltage	V_{IL_F}	$V_{SS} - 0.3$	$0.35 \times V_{DDE}$	V
14	Medium and slow I/O input high voltage	V_{IH_S}	$0.65 \times V_{DDEH}$	$V_{DDEH} + 0.3$	V
15	Medium and slow I/O input low voltage	V_{IL_S}	$V_{SS} - 0.3$	$0.35 \times V_{DDEH}$	V
16	Fast input hysteresis	V_{HYS_F}	$0.1 \times V_{DDE}$		V
17	Medium and slow I/O input hysteresis	V_{HYS_S}	$0.1 \times V_{DDEH}$		V
18	Analog input voltage	V_{INDC}	$V_{SSA} - 0.3$	$V_{DDA} + 0.3$	V
19	Fast output high voltage (I_{OH_F} = –2.0 mA)	V_{OH_F}	$0.8 \times V_{DDE}$	—	V
20	Slow and medium output high voltage I_{OH_S} = –2.0 mA I_{OH_S} = –1.0 mA	V_{OH_S}	$0.80 \times V_{DDEH}$ $0.85 \times V_{DDEH}$	—	V
21	Fast output low voltage (I_{OL_F} = 2.0 mA)	V_{OL_F}	—	$0.2 \times V_{DDE}$	V
22	Slow and medium output low voltage I_{OL_S} = 2.0 mA I_{OL_S} = 1.0 mA	V_{OL_S}	—	 $0.20 \times V_{DDEH}$ $0.15 \times V_{DDEH}$	V
23	Load capacitance (fast I/O) [5] DSC (SIU_PCR[8:9]) = 0b00 = 0b01 = 0b10 = 0b11	C_L	 — — — —	 10 20 30 50	 pF pF pF pF
24	Input capacitance (digital pins)	C_{IN}	—	7	pF
25	Input capacitance (analog pins)	C_{IN_A}	—	10	pF
26	Input capacitance: (Shared digital and analog pins AN[12]_MA[0]_$\overline{SDS}$, AN[13]_MA[1]_SDO, AN[14]_MA[2]_SDI, and AN[15]_FCK)	C_{IN_M}	—	12	pF

Table 9. DC Electrical Specifications ($T_A = T_L$ to T_H) (continued)

Spec	Characteristic	Symbol	Min	Max.	Unit
27a	Operating current 1.5 V supplies @ 135 MHz: [6]				
	V_{DD} (including V_{DDF} max current) @1.65 V typical use [7, 8]	I_{DD}	—	550	mA
	V_{DD} (including V_{DDF} max current) @1.35 V typical use [7, 8]	I_{DD}	—	450	mA
	V_{DD} (including V_{DDF} max current) @1.65 V high use [8, 9]	I_{DD}	—	600	mA
	V_{DD} (including V_{DDF} max current) @1.35 V high use [8, 9]	I_{DD}	—	490	mA
27b	Operating current 1.5 V supplies @ 114 MHz: [6]				
	V_{DD} (including V_{DDF} max current) @1.65 V typical use [7, 8]	I_{DD}	—	460	mA
	V_{DD} (including V_{DDF} max current) @1.35 V typical use [7, 8]	I_{DD}	—	380	mA
	V_{DD} (including V_{DDF} max current) @1.65 V high use [8, 9]	I_{DD}	—	520	mA
	V_{DD} (including V_{DDF} max current) @1.35 V high use [8, 9]	I_{DD}	—	420	mA
27c	Operating current 1.5 V supplies @ 82 MHz: [6]				
	V_{DD} (including V_{DDF} max current) @1.65 V typical use [7, 8]	I_{DD}	—	350	mA
	V_{DD} (including V_{DDF} max current) @1.35 V typical use [7, 8]	I_{DD}	—	290	mA
	V_{DD} (including V_{DDF} max current) @1.65 V high use [8, 9]	I_{DD}	—	400	mA
	V_{DD} (including V_{DDF} max current) @1.35 V high use [8, 9]	I_{DD}	—	330	mA
27d	RAM standby current.[10]				
	I_{DD_STBY} @ 25° C				
	V_{STBY} @ 0.8 V	I_{DD_STBY}	—	20	µA
	V_{STBY} @ 1.0 V	I_{DD_STBY}	—	30	µA
	V_{STBY} @ 1.2 V	I_{DD_STBY}	—	50	µA
	I_{DD_STBY} @ 60° C				
	V_{STBY} @ 0.8 V	I_{DD_STBY}	—	70	µA
	V_{STBY} @ 1.0 V	I_{DD_STBY}	—	100	µA
	V_{STBY} @ 1.2 V	I_{DD_STBY}	—	200	µA
	I_{DD_STBY} @ 150° C (Tj)				
	V_{STBY} @ 0.8 V	I_{DD_STBY}	—	1200	µA
	V_{STBY} @ 1.0 V	I_{DD_STBY}	—	1500	µA
	V_{STBY} @ 1.2 V	I_{DD_STBY}	—	2000	µA
28	Operating current 3.3 V supplies @ f_{MAX} MHz				
	V_{DD33} [11]	I_{DD_33}	—	2 + (values derived from procedure of footnote [11])	mA
	V_{FLASH}	I_{VFLASH}	—	10	mA
	V_{DDSYN}	I_{DDSYN}	—	15	mA
29	Operating current 5.0 V supplies (12 MHz ADCLK):				
	V_{DDA} (V_{DDA0} + V_{DDA1})	I_{DD_A}	—	20.0	mA
	Analog reference supply current (V_{RH}, V_{RL})	I_{REF}	—	1.0	mA
	V_{PP}	I_{PP}	—	25.0	mA

Table 9. DC Electrical Specifications ($T_A = T_L$ to T_H) (continued)

Spec	Characteristic	Symbol	Min	Max.	Unit
30	Operating current V_{DDE} supplies: [12]				
	V_{DDEH1}	I_{DD1}	—	Refer to footnote [12]	mA
	V_{DDE2}	I_{DD2}	—		mA
	V_{DDE3}	I_{DD3}	—		mA
	V_{DDEH4}	I_{DD4}	—		mA
	V_{DDE5}	I_{DD5}	—		mA
	V_{DDEH6}	I_{DD6}	—		mA
	V_{DDE7}	I_{DD7}	—		mA
	V_{DDEH8}	I_{DD8}	—		mA
	V_{DDEH9}	I_{DD9}	—		mA
31	Fast I/O weak pullup current [13]	I_{ACT_F}			
	1.62–1.98 V		10	110	µA
	2.25–2.75 V		20	130	µA
	3.00–3.60 V		20	170	µA
	Fast I/O weak pulldown current [13]				
	1.62–1.98 V		10	100	µA
	2.25–2.75 V		20	130	µA
	3.00–3.60 V		20	170	µA
32	Slow and medium I/O weak pullup/down current [13]	I_{ACT_S}			
	3.0–3.6 V		10	150	µA
	4.5–5.5 V		20	170	µA
33	I/O input leakage current [14]	I_{INACT_D}	–2.5	2.5	µA
34	DC injection current (per pin)	I_{IC}	–2.0	2.0	mA
35	Analog input current, channel off [15]	I_{INACT_A}	–150	150	nA
35a	Analog input current, shared analog / digital pins (AN[12], AN[13], AN[14], AN[15])	I_{INACT_AD}	–2.5	2.5	µA
36	V_{SS} to V_{SSA} differential voltage [16]	$V_{SS} - V_{SSA}$	–100	100	mV
37	Analog reference low voltage	V_{RL}	$V_{SSA} - 0.1$	$V_{SSA} + 0.1$	V
38	V_{RL} differential voltage	$V_{RL} - V_{SSA}$	–100	100	mV
39	Analog reference high voltage	V_{RH}	$V_{DDA} - 0.1$	$V_{DDA} + 0.1$	V
40	V_{REF} differential voltage	$V_{RH} - V_{RL}$	4.5	5.25	V
41	V_{SSSYN} to V_{SS} differential voltage	$V_{SSSYN} - V_{SS}$	–50	50	mV
42	V_{RCVSS} to V_{SS} differential voltage	$V_{RCVSS} - V_{SS}$	–50	50	mV
43	V_{DDF} to V_{DD} differential voltage	$V_{DDF} - V_{DD}$	–100	100	mV
43a	V_{RC33} to V_{DDSYN} differential voltage	$V_{RC33} - V_{DDSYN}$	–0.1	0.1 [17]	V
44	Analog input differential signal range (with common mode 2.5 V)	V_{IDIFF}	–2.5	2.5	V
45	Operating temperature range, ambient (packaged)	$T_A = (T_L$ to $T_H)$	T_L	T_H	°C
46	Slew rate on power-supply pins	—	—	50	V/ms

1 V_{DDE2} and V_{DDE3} are limited to 2.25–3.6 V only if SIU_ECCR[EBTS] = 0; V_{DDE2} and V_{DDE3} have a range of 1.6–3.6 V if SIU_ECCR[EBTS] = 1.

[2] $|V_{DDA0} - V_{DDA1}|$ must be < 0.1 V.

[3] V_{PP} can drop to 3.0 V during read operations.

[4] If standby operation is not required, connect V_{STBY} to ground.

[5] Applies to CLKOUT, external bus pins, and Nexus pins.

[6] Maximum average RMS DC current.

[7] Average current measured on automotive benchmark.

[8] Peak currents can be higher on specialized code.

[9] High use current measured while running optimized SPE assembly code with all code and data 100% locked in cache (0% miss rate) with all channels of the eMIOS and eTPU running autonomously, plus the eDMA transferring data continuously from SRAM to SRAM. Higher currents are possible if an idle loop that crosses cache lines is run from cache. Write code to avoid this condition.

[10] The current specification relates to average standby operation after SRAM has been loaded with data. For power up current see Section 3.7, “Power-Up/Down Sequencing”, Figure 2.

[11] Power requirements for the V_{DD33} supply depend on the frequency of operation, load of all I/O pins, and the voltages on the I/O segments. Refer to Table 11 for values to calculate the power dissipation for a specific operation.

[12] Power requirements for each I/O segment are dependent on the frequency of operation and load of the I/O pins on a particular I/O segment, and the voltage of the I/O segment. Refer to Table 10 for values to calculate power dissipation for specific operation. The total power consumption of an I/O segment is the sum of the individual power consumptions for each pin on the segment.

[13] Absolute value of current, measured at V_{IL} and V_{IH}.

[14] Weak pullup/down inactive. Measured at V_{DDE} = 3.6 V and V_{DDEH} = 5.25 V. Applies to pad types: pad_fc, pad_sh, and pad_mh.

[15] Maximum leakage occurs at maximum operating temperature. Leakage current decreases by approximately one-half for each 8 ^{o}C to 12 ^{o}C, in the ambient temperature range of 50 ^{o}C to 125 ^{o}C. Applies to pad types: pad_a and pad_ae.

[16] V_{SSA} refers to both V_{SSA0} and V_{SSA1}. $|V_{SSA0} - V_{SSA1}|$ must be < 0.1 V.

[17] Up to 0.6 V during power up and power down.

3.8.1 I/O Pad Current Specifications

The power consumption of an I/O segment depends on the usage of the pins on a particular segment. The power consumption is the sum of all output pin currents for a segment. The output pin current can be calculated from Table 10 based on the voltage, frequency, and load on the pin. Use linear scaling to calculate pin currents for voltage, frequency, and load parameters that fall outside the values given in Table 10.

Table 10. I/O Pad Average DC Current ($T_A = T_L$ to T_H)[1]

Spec	Pad Type	Symbol	Frequency (MHz)	Load[2] (pF)	Voltage (V)	Drive Select / Slew Rate Control Setting	Current (mA)
1	Slow	I_{DRV_SH}	25	50	5.25	11	8.0
2			10	50	5.25	01	3.2
3			2	50	5.25	00	0.7
4			2	200	5.25	00	2.4
5	Medium	I_{DRV_MH}	50	50	5.25	11	17.3
6			20	50	5.25	01	6.5
7			3.33	50	5.25	00	1.1
8			3.33	200	5.25	00	3.9
9	Fast	I_{DRV_FC}	66	10	3.6	00	2.8
10			66	20	3.6	01	5.2
11			66	30	3.6	10	8.5
12			66	50	3.6	11	11.0
13			66	10	1.98	00	1.6
14			66	20	1.98	01	2.9
15			66	30	1.98	10	4.2
16			66	50	1.98	11	6.7
17			56	10	3.6	00	2.4
18			56	20	3.6	01	4.4
19			56	30	3.6	10	7.2
20			56	50	3.6	11	9.3
21			56	10	1.98	00	1.3
22			56	20	1.98	01	2.5
23			56	30	1.98	10	3.5
24			56	50	1.98	11	5.7
25			40	10	3.6	00	1.7
26			40	20	3.6	01	3.1
27			40	30	3.6	10	5.1
28			40	50	3.6	11	6.6
29			40	10	1.98	00	1.0
30			40	20	1.98	01	1.8
31			40	30	1.98	10	2.5
32			40	50	1.98	11	4.0

1 These values are estimates from simulation and are not tested. Currents apply to output pins only.

2 All loads are lumped.

3.8.2 I/O Pad V_{DD33} Current Specifications

The power consumption of the V_{DD33} supply dependents on the usage of the pins on all I/O segments. The power consumption is the sum of all input and output pin V_{DD33} currents for all I/O segments. The output pin V_{DD33} current can be calculated from Table 11 based on the voltage, frequency, and load on all fast (pad_fc) pins. The input pin V_{DD33} current can be calculated from Table 11 based on the voltage, frequency, and load on all pad_sh and pad_mh pins. Use linear scaling to calculate pin currents for voltage, frequency, and load parameters that fall outside the values given in Table 11.

Table 11. V_{DD33} Pad Average DC Current ($T_A = T_L$ to T_H) [1]

Spec	Pad Type	Symbol	Frequency (MHz)	Load [2] (pF)	V_{DD33} (V)	V_{DDE} (V)	Drive Select	Current (mA)
Inputs								
1	Slow	I_{33_SH}	66	0.5	3.6	5.5	NA	0.003
2	Medium	I_{33_MH}	66	0.5	3.6	5.5	NA	0.003
Outputs								
3	Fast	I_{33_FC}	66	10	3.6	3.6	00	0.35
4			66	20	3.6	3.6	01	0.53
5			66	30	3.6	3.6	10	0.62
6			66	50	3.6	3.6	11	0.79
7			66	10	3.6	1.98	00	0.35
8			66	20	3.6	1.98	01	0.44
9			66	30	3.6	1.98	10	0.53
10			66	50	3.6	1.98	11	0.70
11			56	10	3.6	3.6	00	0.30
12			56	20	3.6	3.6	01	0.45
13			56	30	3.6	3.6	10	0.52
14			56	50	3.6	3.6	11	0.67
15			56	10	3.6	1.98	00	0.30
16			56	20	3.6	1.98	01	0.37
17			56	30	3.6	1.98	10	0.45
18			56	50	3.6	1.98	11	0.60
19			40	10	3.6	3.6	00	0.21
20			40	20	3.6	3.6	01	0.31
21			40	30	3.6	3.6	10	0.37
22			40	50	3.6	3.6	11	0.48
23			40	10	3.6	1.98	00	0.21
24			40	20	3.6	1.98	01	0.27
25			40	30	3.6	1.98	10	0.32
26			40	50	3.6	1.98	11	0.42

1 These values are estimated from simulation and not tested. Currents apply to output pins for the fast pads only and to input pins for the slow and medium pads only.

2 All loads are lumped.

3.9 Oscillator and FMPLL Electrical Characteristics

Table 12. FMPLL Electrical Specifications

(V_{DDSYN} = 3.0–3.6 V; V_{SS} = V_{SSSYN} = 0.0 V; T_A = T_L to T_H)

Spec	Characteristic	Symbol	Minimum	Maximum	Unit
1	PLL reference frequency range: [1] Crystal reference (20)[2] Crystal reference (40)[3] External reference (20)[2] External reference (40)[3] Dual controller (1:1 mode)	 $f_{ref_crystal}$ $f_{ref_crystal}$ f_{ref_ext} f_{ref_ext} $f_{ref_1:1}$	 8 > 20 8 > 20 24	 ≤ 20 40 ≤ 20 40 $f_{sys} \div 2$	MHz
2	System frequency [4]	f_{sys}	$f_{ICO(MIN)} \div 2^{RFD}$	f_{MAX} [5]	MHz
3	System clock period	t_{CYC}	—	$1 \div f_{sys}$	ns
4	Loss of reference frequency [6]	f_{LOR}	100	1000	kHz
5	Self-clocked mode (SCM) frequency [7]	f_{SCM}	7.4	17.5	MHz
6	EXTAL input high voltage crystal mode [8] All other modes [dual controller (1:1), bypass, external reference]	V_{IHEXT} V_{IHEXT}	V_{XTAL} + 0.4 V $(V_{DDE5} \div 2)$ + 0.4 V	— —	V V
7	EXTAL input low voltage crystal mode [9] All other modes [dual controller (1:1), bypass, external reference]	V_{ILEXT} V_{ILEXT}	— —	V_{XTAL} – 0.4 V $(V_{DDE5} \div 2)$ – 0.4 V	V V
8	XTAL current [10]	I_{XTAL}	2	6	mA
9	Total on-chip stray capacitance on XTAL	C_{S_XTAL}	—	1.5	pF
10	Total on-chip stray capacitance on EXTAL	C_{S_EXTAL}	—	1.5	pF
11	Crystal manufacturer's recommended capacitive load	C_L	Refer to crystal specification	Refer to crystal specification	pF
12	Discrete load capacitance to connect to EXTAL	C_{L_EXTAL}	—	$(2 \times C_L) - C_{S_EXTAL} - C_{PCB_EXTAL}$ [11]	pF
13	Discrete load capacitance to connect to XTAL	C_{L_XTAL}	—	$(2 \times C_L) - C_{S_XTAL} - C_{PCB_XTAL}$ [11]	pF
14	PLL lock time [12]	t_{lpll}	—	750	µs
15	Dual controller (1:1) clock skew (between CLKOUT and EXTAL) [13, 14]	t_{skew}	–2	2	ns
16	Duty cycle of reference	t_{DC}	40	60	%
17	Frequency unLOCK range	f_{UL}	–4.0	4.0	% f_{SYS}
18	Frequency LOCK range	f_{LCK}	–2.0	2.0	% f_{SYS}

Table 12. FMPLL Electrical Specifications (continued)

(V_{DDSYN} = 3.0–3.6 V; V_{SS} = V_{SSSYN} = 0.0 V; T_A = T_L to T_H)

Spec	Characteristic	Symbol	Minimum	Maximum	Unit
19	CLKOUT period jitter, measured at f_{SYS} max: [15, 16] Peak-to-peak jitter (clock edge to clock edge) Long term jitter (averaged over a 2 ms interval)	C_{JITTER}	 — —	 5.0 0.01	% f_{CLKOUT}
20	Frequency modulation range limit [17] (do not exceed f_{sys} maximum)	C_{MOD}	0.8	2.4	$\%f_{SYS}$
21	ICO frequency $f_{ico} = [f_{ref_crystal} \times (MFD + 4)] \div (PREDIV + 1)$ [18] $f_{ico} = [f_{ref_ext} \times (MFD + 4)] \div (PREDIV + 1)$	f_{ico}	48	f_{MAX}	MHz
22	Predivider output frequency (to PLL)	f_{PREDIV}	4	20 [19]	MHz

1 Nominal crystal and external reference values are worst-case not more than 1%. The device operates correctly if the frequency remains within ± 5% of the specification limit. This tolerance range allows for a slight frequency drift of the crystals over time. The designer must thoroughly understand the drift margin of the source clock.

2 The 8–20 MHz crystal or external reference values have PLLCFG[2] pulled low.

3 The 20–40 MHz crystal and external reference values have PLLCFG[2] pulled high, and the minimum frequency must be greater than 20 MHz. Use the 8–20 MHz setting (PLLCFG[2] pulled low) if a 20 MHz crystal or external reference is required. To exit RESET when using 40 MHz, set PLLCFG[2] to 1.

4 All internal registers retain data at 0 Hz.

5 Up to the maximum frequency rating of the device (refer to Table 1).

6 Loss of reference frequency is defined as the reference frequency detected internally, which transitions the PLL into self-clocked mode.

7 The PLL operates at self-clocked mode (SCM) frequency when the reference frequency falls below f_{LOR}. SCM frequency is measured on the CLKOUT ball with the divider set to divide-by-two of the system clock.
NOTE: In SCM, the MFD and PREDIV have no effect and the RFD is bypassed.

8 Use the EXTAL input high voltage parameter when using the FlexCAN oscillator in crystal mode (no quartz crystals or resonators). ($V_{extal} - V_{xtal}$) must be ≥ 400 mV for the oscillator's comparator to produce the output clock.

9 Use the EXTAL input low voltage parameter when using the FlexCAN oscillator in crystal mode (no quartz crystals or resonators). ($V_{xtal} - V_{extal}$) must be ≥ 400 mV for the oscillator's comparator to produce the output clock.

10 I_{xtal} is the oscillator bias current out of the XTAL pin with both EXTAL and XTAL pins grounded.

11 C_{PCB_EXTAL} and C_{PCB_XTAL} are the measured PCB stray capacitances on EXTAL and XTAL, respectively.

12 This specification applies to the period required for the PLL to relock after changing the MFD frequency control bits in the synthesizer control register (SYNCR). From power up with crystal oscillator reference, the lock time also includes the crystal startup time.

13 PLL is operating in 1:1 PLL mode.

14 V_{DDE} = 3.0–3.6 V.

15 Jitter is the average deviation from the programmed frequency measured over the specified interval at maximum f_{sys}. Measurements are made with the device powered by filtered supplies and clocked by a stable external clock signal. Noise injected into the PLL circuitry via V_{DDSYN} and V_{SSSYN} and variation in crystal oscillator frequency increase the jitter percentage for a given interval. CLKOUT divider is set to divide-by-two.

16 Values are with frequency modulation disabled. If frequency modulation is enabled, jitter is the sum of (jitter + Cmod).

17 Modulation depth selected must not result in f_{sys} value greater than the f_{sys} maximum specified value.

18 $f_{sys} = f_{ico} \div (2^{RFD})$.

19 Maximum value for dual controller (1:1) mode is ($f_{MAX} \div 2$) with the predivider set to 1 (FMPLL_SYNCR[PREDIV] = 0b001).

3.10 eQADC Electrical Characteristics

Table 13. eQADC Conversion Specifications ($T_A = T_L$ to T_H)

Spec	Characteristic	Symbol	Minimum	Maximum	Unit
1	ADC clock (ADCLK) frequency [1]	F_{ADCLK}	1	12	MHz
2	Conversion cycles Differential Single ended	CC	 13 + 2 (15) 14 + 2 (16)	 13 + 128 (141) 14 + 128 (142)	ADCLK cycles
3	Stop mode recovery time [2]	T_{SR}	10	—	µs
4	Resolution [3]	—	1.25	—	mV
5	INL: 6 MHz ADC clock	INL6	–4	4	Counts [3]
6	INL: 12 MHz ADC clock	INL12	–8	8	Counts
7	DNL: 6 MHz ADC clock	DNL6	–3 [4]	3 [4]	Counts
8	DNL: 12 MHz ADC clock	DNL12	–6 [4]	6 [4]	Counts
9	Offset error with calibration	OFFWC	–4 [5]	4 [5]	Counts
10	Full-scale gain error with calibration	GAINWC	–8 [6]	8 [6]	Counts
11	Disruptive input injection current [7, 8, 9, 10]	I_{INJ}	–1	1	mA
12	Incremental error due to injection current. All channels are 10 kΩ < Rs <100 kΩ Channel under test has Rs = 10 kΩ, $I_{INJ} = I_{INJMAX}$, I_{INJMIN}	E_{INJ}	–4	4	Counts
13	Total unadjusted error (TUE) for single ended conversions with calibration [11, 12, 13, 14, 15]	TUE	–4	4	Counts

1 Conversion characteristics vary with F_{ADCLK} rate. Reduced conversion accuracy occurs at maximum F_{ADCLK} rate. The maximum value is based on 800 KS/s and the minimum value is based on 20 MHz oscillator clock frequency divided by a maximum 16 factor.

2 Stop mode recovery time begins when the ADC control register enable bits are set until the ADC is ready to perform conversions.

3 At $V_{RH} – V_{RL}$ = 5.12 V, one least significant bit (LSB) = 1.25, mV = one count.

4 Guaranteed 10-bit mono tonicity.

5 The absolute value of the offset error without calibration ≤ 100 counts.

6 The absolute value of the full scale gain error without calibration ≤ 120 counts.

7 Below disruptive current conditions, the channel being stressed has conversion values of: 0x3FF for analog inputs greater than V_{RH}, and 0x000 for values less than V_{RL}. This assumes that $V_{RH} \leq V_{DDA}$ and $V_{RL} \geq V_{SSA}$ due to the presence of the sample amplifier. Other channels are not affected by non-disruptive conditions.

8 Exceeding the limit can cause a conversion error on both stressed and unstressed channels. Transitions within the limit do not affect device reliability or cause permanent damage.

9 Input must be current limited to the value specified. To determine the value of the required current-limiting resistor, calculate resistance values using $V_{POSCLAMP} = V_{DDA}$ + 0.5 V and $V_{NEGCLAMP}$ = – 0.3 V, then use the larger of the calculated values.

10 This condition applies to two adjacent pads on the internal pad.

11 The TUE specification is always less than the sum of the INL, DNL, offset, and gain errors due to canceling errors.

12 TUE does not apply to differential conversions.

13 Measured at 6 MHz ADC clock. TUE with a 12 MHz ADC clock is: –16 counts < TUE < 16 counts.

14 TUE includes all internal device errors such as internal reference variation (75% Ref, 25% Ref).

15 Depending on the input impedance, the analog input leakage current (Table 9. DC Electrical Specifications, spec 35a) can affect the actual TUE measured on analog channels AN[12], AN[13], AN[14], AN[15].

3.11 H7Fa Flash Memory Electrical Characteristics

Table 14. Flash Program and Erase Specifications ($T_A = T_L$ to T_H)

Spec	Flash Program Characteristic	Symbol	Min.	Typical [1]	Initial Max. [2]	Max. [3]	Unit
3	Doubleword (64 bits) program time [4]	$T_{dwprogram}$	—	10	—	500	µs
4	Page program time [4]	$T_{pprogram}$	—	22	44 [5]	500	µs
7	16 KB block pre-program and erase time	$T_{16kpperase}$	—	265	400	5000	ms
9	48 KB block pre-program and erase time	$T_{48kpperase}$	—	345	400	5000	ms
10	64 KB block pre-program and erase time	$T_{64kpperase}$	—	415	500	5000	ms
8	128 KB block pre-program and erase time	$T_{128kpperase}$	—	500	1250	7500	ms
11	Minimum operating frequency for program and erase operations [6]	—	25	—	—	—	MHz

1 Typical program and erase times are calculated at 25 ^{o}C operating temperature using nominal supply values.

2 Initial factory condition: ≤ 100 program/erase cycles, 25 ^{o}C, using a typical supply voltage measured at a minimum system frequency of 80 MHz.

3 The maximum erase time occurs after the specified number of program/erase cycles. This maximum value is characterized but not guaranteed.

4 Actual hardware programming times. This does not include software overhead.

5 Page size is 256 bits (8 words).

6 The read frequency of the flash can range up to the maximum operating frequency. There is no minimum read frequency condition.

Table 15. Flash EEPROM Module Life ($T_A = T_L$ to T_H)

Spec	Characteristic	Symbol	Min.	Typical [1]	Unit
1a	Number of program/erase cycles per block for 16 KB, 48 KB, and 64 KB blocks over the operating temperature range (T_J)	P/E	100,000	—	cycles
1b	Number of program/erase cycles per block for 128 KB blocks over the operating temperature range (T_J)	P/E	1000	100,000	cycles
2	Data retention Blocks with 0–1,000 P/E cycles Blocks with 1,001–100,000 P/E cycles	Retention	 20 5	 — —	years

1 Typical endurance is evaluated at 25^{o} C. Product qualification is performed to the minimum specification. For additional information on the Freescale definition of typical endurance, refer to engineering bulletin EB619 Typical Endurance for Nonvolatile Memory.

Table 16 shows the FLASH_BIU settings versus frequency of operation. Refer to the device reference manual for definitions of these bit fields.

Table 16. FLASH_BIU Settings vs. Frequency of Operation [1]

Maximum Frequency (MHz)	APC	RWSC	WWSC	DPFEN [2]	IPFEN [2]	PFLIM [3]	BFEN [4]
Up to and including 82 MHz [5]	0b001	0b001	0b01	0b00 0b01 0b11	0b00 0b01 0b11	0b000 to 0b110	0b0 0b1
Up to and including 102 MHz [6]	0b001	0b010	0b01	0b00 0b01 0b11	0b00 0b01 0b11	0b000 to 0b110	0b0 0b1
Up to and including 135 MHz [7]	0b010	0b011	0b01	0b00 0b01 0b11	0b00 0b01 0b11	0b000 to 0b110	0b0 0b1
Default setting after reset	0b111	0b111	0b11	0b00	0b00	0b000	0b0

1 Illegal combinations exist. Use entries from the same row in this table.
2 For maximum flash performance, set to 0b11.
3 For maximum flash performance, set to 0b110.
4 For maximum flash performance, set to 0b1.
5 82 MHz parts allow for 80 MHz system clock + 2% frequency modulation (FM).
6 102 MHz parts allow for 100 MHz system clock + 2% FM.
7 135 MHz parts allow for 132 MHz system clock + 2% FM.

3.12 AC Specifications

3.12.1 Pad AC Specifications

Table 17. Pad AC Specifications (V_{DDEH} = 5.0 V, V_{DDE} = 1.8 V) [1]

Spec	Pad	SRC / DSC (binary)	Out Delay [2, 3, 4] (ns)	Rise / Fall [4, 5] (ns)	Load Drive (pF)
1	Slow high voltage (SH)	11	26	15	50
			82	60	200
		01	75	40	50
			137	80	200
		00	377	200	50
			476	260	200
2	Medium high voltage (MH)	11	16	8	50
			43	30	200
		01	34	15	50
			61	35	200
		00	192	100	50
			239	125	200

Table 17. Pad AC Specifications (V_{DDEH} = 5.0 V, V_{DDE} = 1.8 V) [1] (continued)

Spec	Pad	SRC / DSC (binary)	Out Delay [2, 3, 4] (ns)	Rise / Fall [4, 5] (ns)	Load Drive (pF)
3	Fast	00	3.1	2.7	10
		01		2.5	20
		10		2.4	30
		11		2.3	50
4	Pullup/down (3.6 V max)	—	—	7500	50
5	Pullup/down (5.5 V max)	—	—	9000	50

1 These are worst-case values that are estimated from simulation (not tested). The values in the table are simulated at: V_{DD} = 1.35–1.65 V; V_{DDE} = 1.62–1.98 V; V_{DDEH} = 4.5–5.25 V; V_{DD33} and V_{DDSYN} = 3.0–3.6 V; and T_A = T_L to T_H.

2 This parameter is supplied for reference and is guaranteed by design (not tested).

3 The output delay is shown in Figure 4. To calculate the output delay with respect to the system clock, add a maximum of one system clock to the output delay.

4 The output delay and rise and fall are measured to 20% or 80% of the respective signal.

5 This parameter is guaranteed by characterization rather than 100% tested.

Table 18. Derated Pad AC Specifications (V_{DDEH} = 3.3 V, V_{DDE} = 3.3 V) [1]

Spec	Pad	SRC/DSC (binary)	Out Delay [2, 3, 4] (ns)	Rise / Fall [3, 5] (ns)	Load Drive (pF)
1	Slow high voltage (SH)	11	39	23	50
			120	87	200
		01	101	52	50
			188	111	200
		00	507	248	50
			597	312	200
2	Medium high voltage (MH)	11	23	12	50
			64	44	200
		01	50	22	50
			90	50	200
		00	261	123	50
			305	156	200
3	Fast	00	3.2	2.4	10
		01		2.2	20
		10		2.1	30
		11		2.1	50
4	Pullup/down (3.6 V max)	—	—	7500	50
5	Pullup/down (5.5 V max)	—	—	9500	50

1 These are worst-case values that are estimated from simulation (not tested). The values in the table are simulated at: V_{DD} = 1.35–1.65 V; V_{DDE} = 3.0–3.6 V; V_{DDEH} = 3.0–3.6 V; V_{DD33} and V_{DDSYN} = 3.0–3.6 V; and T_A = T_L to T_H.

2 This parameter is supplied for reference and guaranteed by design (not tested).

3 The output delay, and the rise and fall, are calculated to 20% or 80% of the respective signal.

4 The output delay is shown in Figure 4. To calculate the output delay with respect to the system clock, add a maximum of one system clock to the output delay.

5 This parameter is guaranteed by characterization rather than 100% tested.

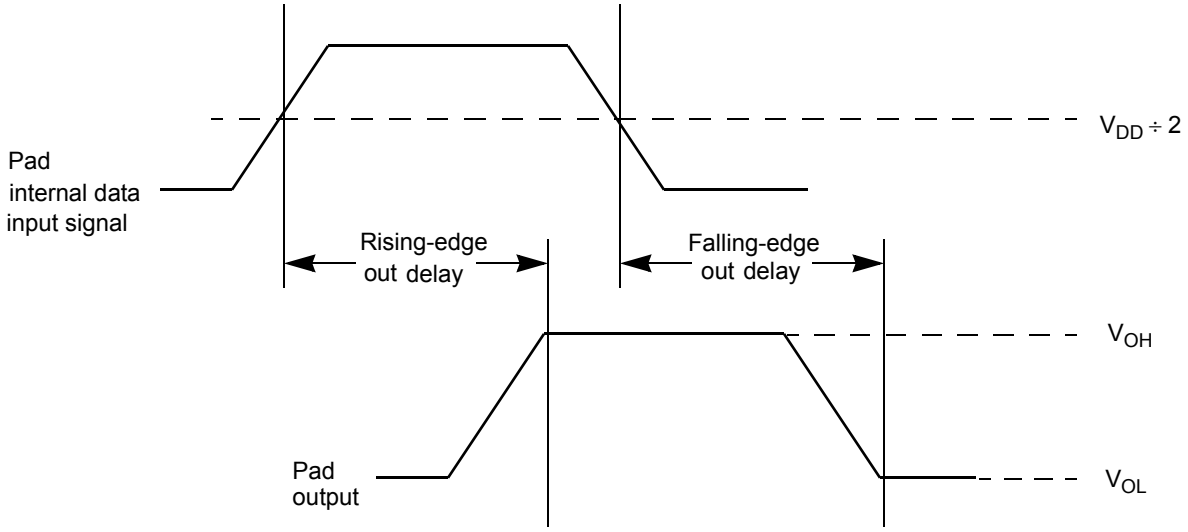


Figure 4. Pad Output Delay

3.13 AC Timing

3.13.1 Reset and Configuration Pin Timing

Table 19. Reset and Configuration Pin Timing [1]

Spec	Characteristic	Symbol	Min.	Max.	Unit
1	$\overline{\text{RESET}}$ pulse width	t_{RPW}	10	—	t_{CYC}
2	$\overline{\text{RESET}}$ glitch detect pulse width	t_{GPW}	2	—	t_{CYC}
3	PLLCFG, BOOTCFG, WKPCFG, $\overline{\text{RSTCFG}}$ setup time to $\overline{\text{RSTOUT}}$ valid	t_{RCSU}	10	—	t_{CYC}
4	PLLCFG, BOOTCFG, WKPCFG, $\overline{\text{RSTCFG}}$ hold time from $\overline{\text{RSTOUT}}$ valid	t_{RCH}	0	—	t_{CYC}

1 Reset timing specified at: V_{DDEH} = 3.0–5.25 V and $T_A = T_L$ to T_H.

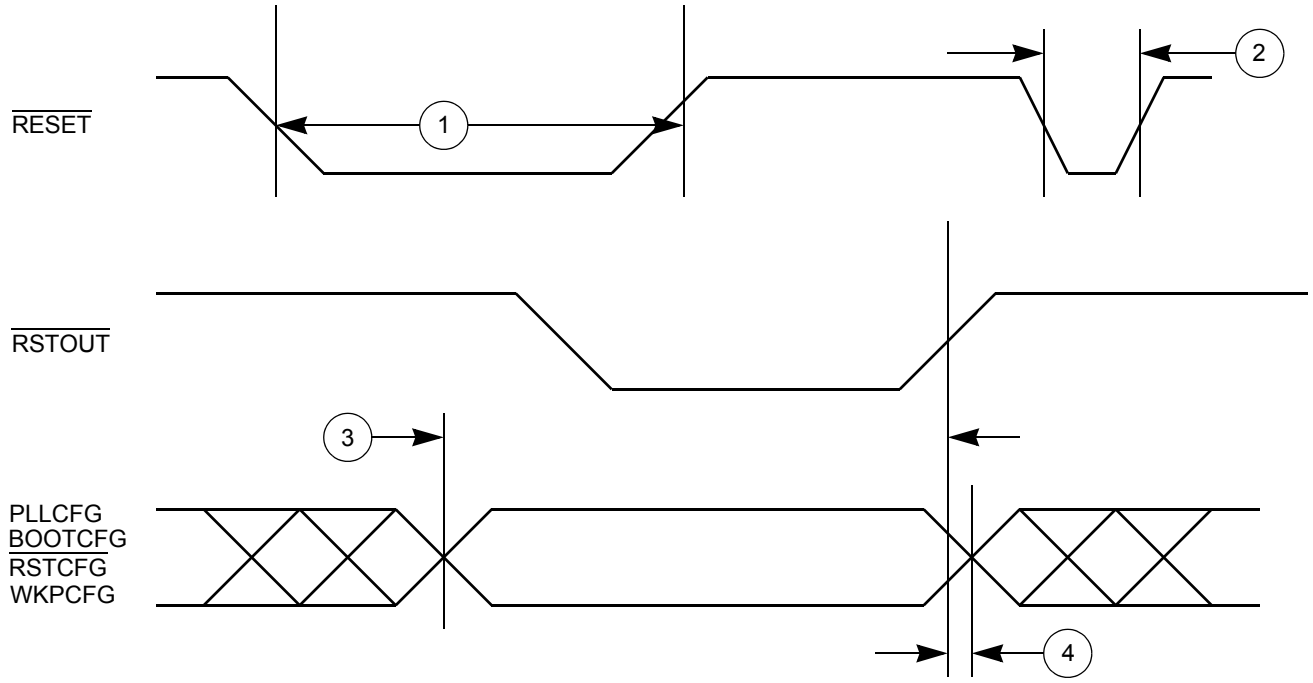


Figure 5. Reset and Configuration Pin Timing

3.13.2 IEEE 1149.1 Interface Timing

Table 20. JTAG Pin AC Electrical Characteristics [1]

Spec	Characteristic	Symbol	Min.	Max.	Unit
1	TCK cycle time	t_{JCYC}	100	—	ns
2	TCK clock pulse width (measured at $V_{DDE} \div 2$)	t_{JDC}	40	60	ns
3	TCK rise and fall times (40% to 70%)	$t_{TCKRISE}$	—	3	ns
4	TMS, TDI data setup time	t_{TMSS}, t_{TDIS}	5	—	ns
5	TMS, TDI data hold time	t_{TMSH}, t_{TDIH}	25	—	ns
6	TCK low to TDO data valid	t_{TDOV}	—	20	ns
7	TCK low to TDO data invalid	t_{TDOI}	0	—	ns
8	TCK low to TDO high impedance	t_{TDOHZ}	—	20	ns
9	JCOMP assertion time	t_{JCMPPW}	100	—	ns
10	JCOMP setup time to TCK low	t_{JCMPS}	40	—	ns
11	TCK falling-edge to output valid	t_{BSDV}	—	50	ns
12	TCK falling-edge to output valid out of high impedance	t_{BSDVZ}	—	50	ns
13	TCK falling-edge to output high impedance (Hi-Z)	t_{BSDHZ}	—	50	ns
14	Boundary scan input valid to TCK rising-edge	t_{BSDST}	50	—	ns
15	TCK rising-edge to boundary scan input invalid	t_{BSDHT}	50	—	ns

[1] These specifications apply to JTAG boundary scan only. JTAG timing specified at: V_{DDE} = 3.0–3.6 V and $T_A = T_L$ to T_H. Refer to Table 21 for Nexus specifications.

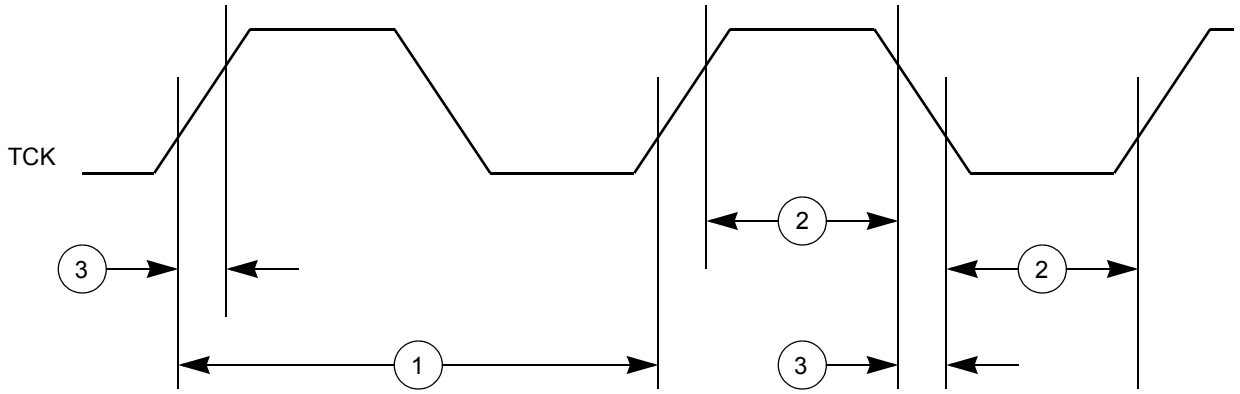


Figure 6. JTAG Test Clock Input Timing

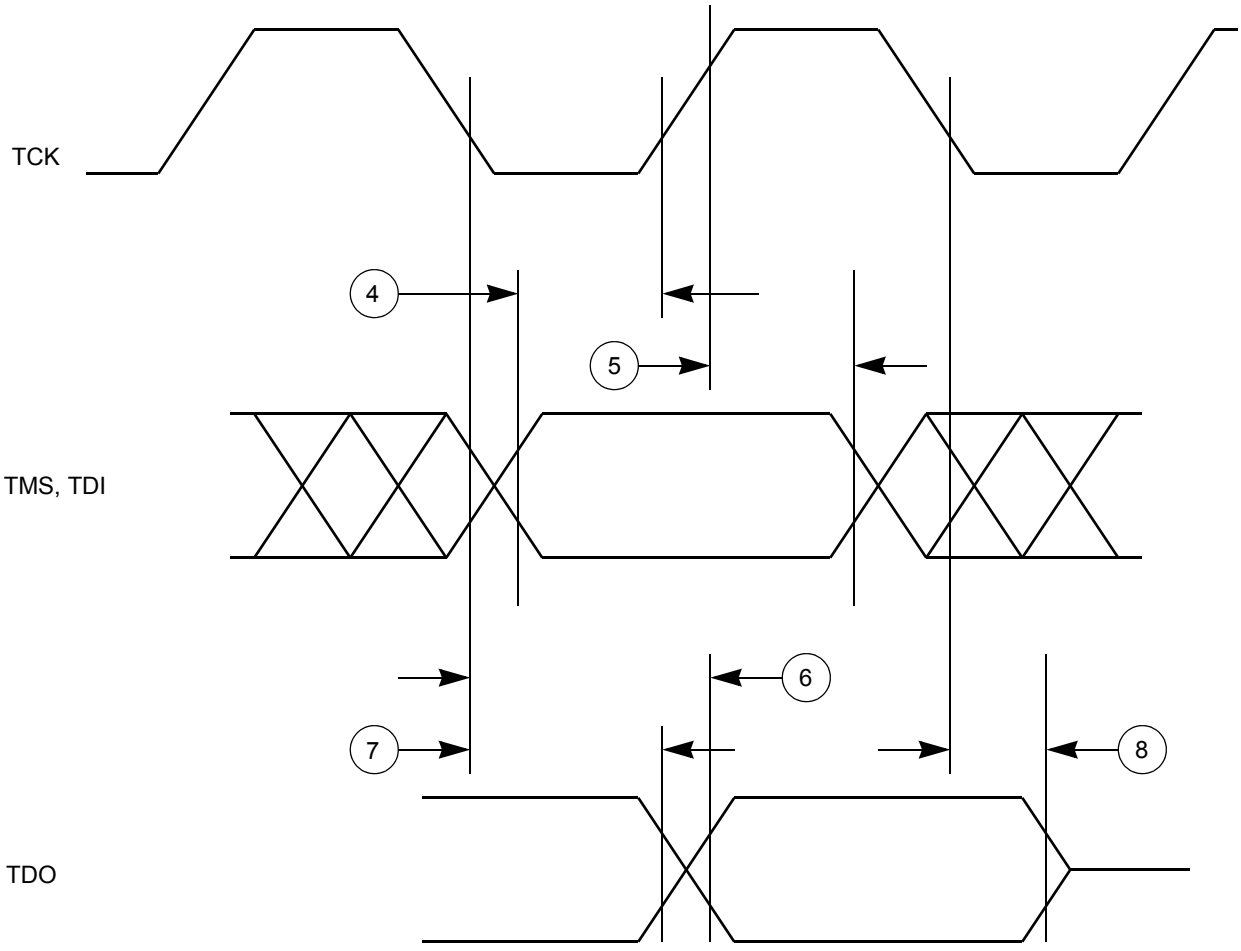


Figure 7. JTAG Test Access Port Timing

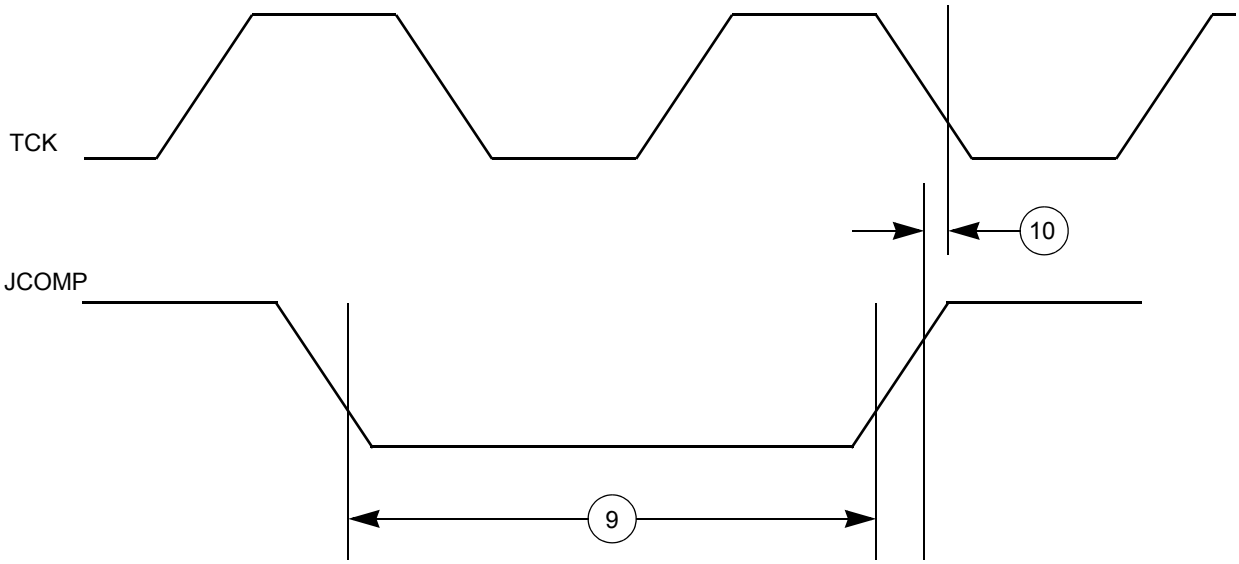


Figure 8. JTAG JCOMP Timing

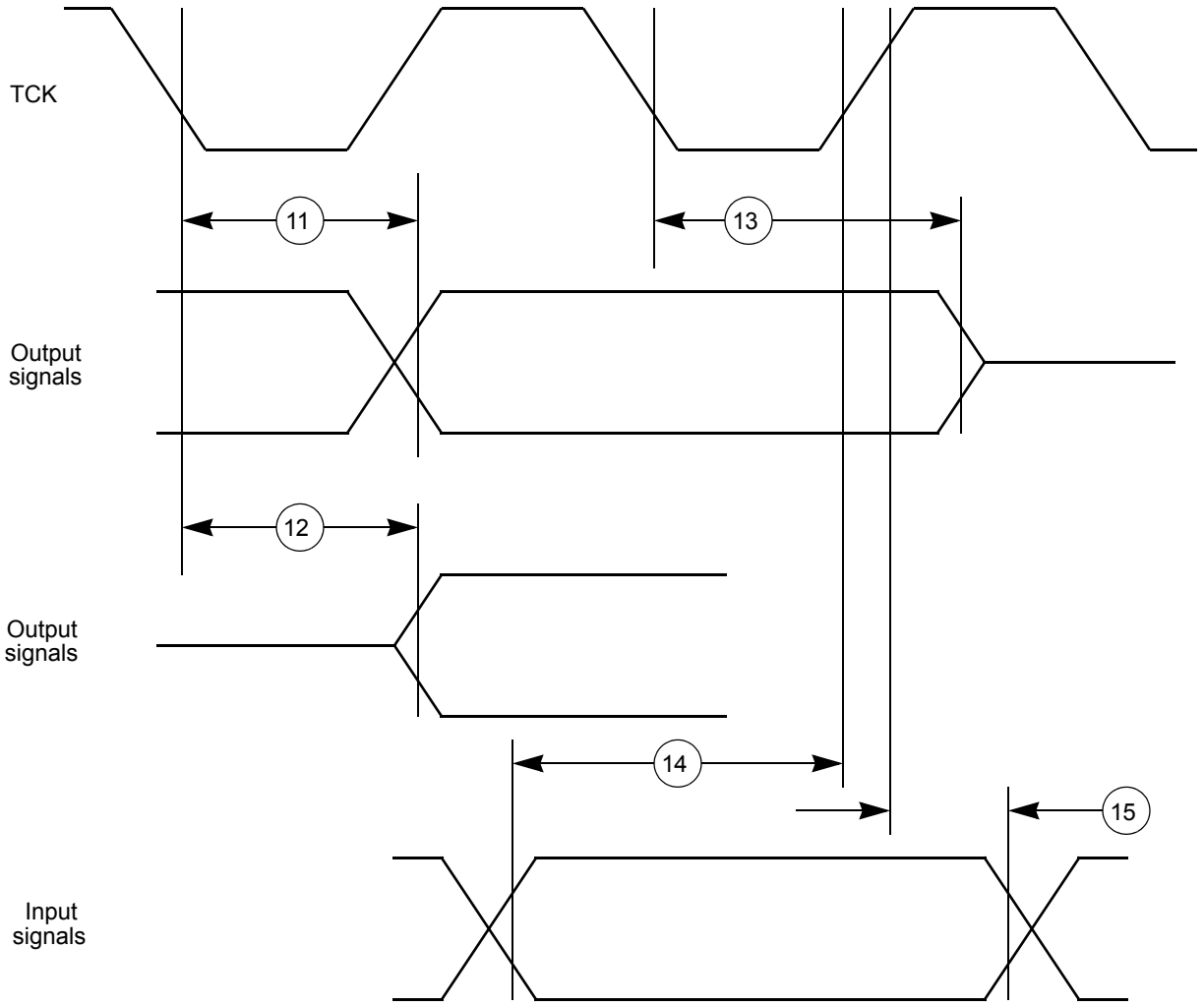


Figure 9. JTAG Boundary Scan Timing

3.13.3 Nexus Timing

Table 21. Nexus Debug Port Timing [1]

Spec	Characteristic	Symbol	Min.	Max.	Unit
1	MCKO cycle time	t_{MCYC}	1 [2]	8	t_{CYC}
2	MCKO duty cycle	t_{MDC}	40	60	%
3	MCKO low to MDO data valid [3]	t_{MDOV}	–1.5	3.0	ns
4	MCKO low to $\overline{\text{MSEO}}$ data valid [3]	t_{MSEOV}	–1.5	3.0	ns
5	MCKO low to $\overline{\text{EVTO}}$ data valid [3]	t_{EVTOV}	–1.5	3.0	ns
6	$\overline{\text{EVTI}}$ pulse width	t_{EVTIPW}	4.0	—	t_{TCYC}
7	$\overline{\text{EVTO}}$ pulse width	t_{EVTOPW}	1	—	t_{MCYC}
8	TCK cycle time	t_{TCYC}	4 [4]	—	t_{CYC}
9	TCK duty cycle	t_{TDC}	40	60	%
10	TDI, TMS data setup time	t_{NTDIS}, t_{NTMSS}	8	—	ns
11	TDI, TMS data hold time	t_{NTDIH}, t_{NTMSH}	5	—	ns
12	TCK low to TDO data valid V_{DDE} = 2.25–3.0 V V_{DDE} = 3.0–3.6 V	t_{JOV}	 0 0	 12 10	 ns ns
13	$\overline{\text{RDY}}$ valid to MCKO [5]	—	—	—	—

1 JTAG specifications apply when used for debug functionality. All Nexus timing relative to MCKO is measured from 50% of MCKO and 50% of the respective signal. Nexus timing specified at V_{DD} = 1.35–1.65 V, V_{DDE} = 2.25–3.6 V, V_{DD33} and V_{DDSYN} = 3.0–3.6 V, T_A = T_L to T_H, and CL = 30 pF with DSC = 0b10.

2 The Nexus AUX port runs up to 82 MHz. Set NPC_PCR[MCKO_DIV] to divide-by-two if the system frequency is greater than 82 MHz.

3 MDO, $\overline{\text{MSEO}}$, and $\overline{\text{EVTO}}$ data is held valid until the next MCKO low cycle occurs.

4 Limit the maximum frequency to approximately 16 MHz (V_{DDE} = 2.25–3.0 V) or 20 MHz (V_{DDE} = 3.0–3.6 V) to meet the timing specification for t_{JOV} of [0.2 x t_{JCYC}] as outlined in the IEEE-ISTO 5001-2003 specification.

5 The $\overline{\text{RDY}}$ pin timing is asynchronous to MCKO and is guaranteed by design to function correctly.

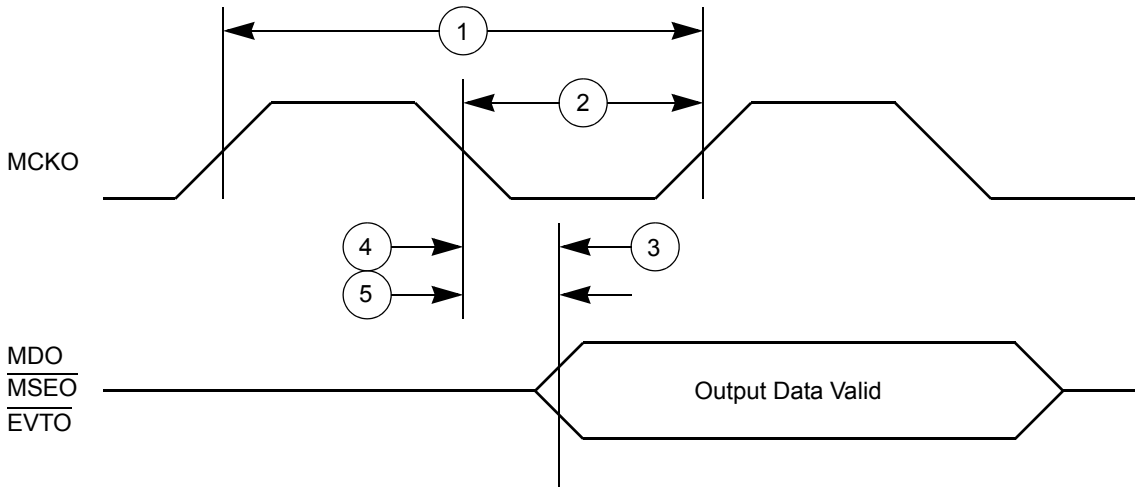


Figure 10. Nexus Output Timing

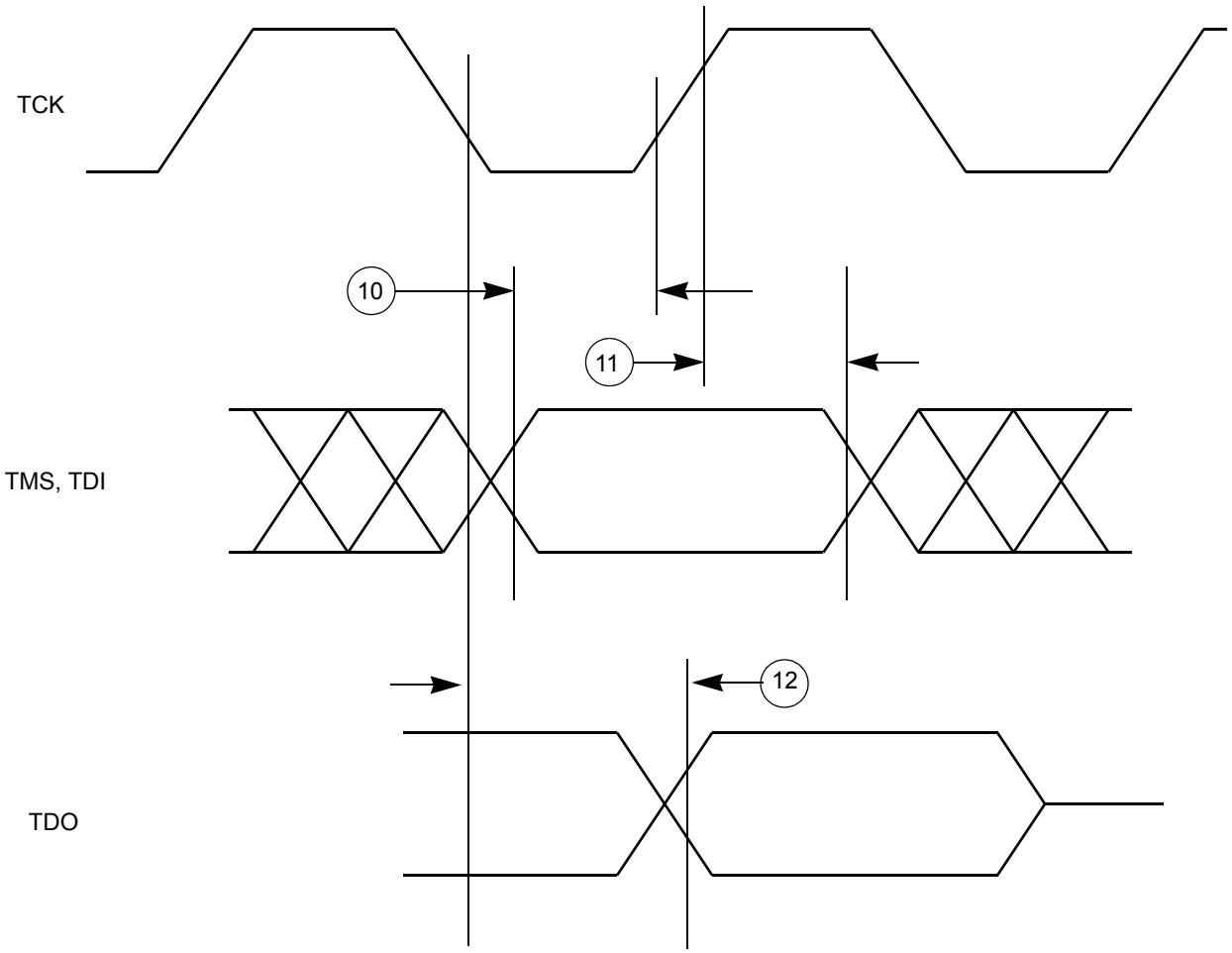


Figure 11. Nexus TDI, TMS, TDO Timing

3.13.4 External Bus Interface (EBI) Timing

Table 22 lists the timing information for the external bus interface (EBI).

Table 22. Bus Operation Timing[1]

Spec	Characteristic and Description	Symbol	External Bus Frequency [2, 3]						Unit	Notes
			40 MHz		56 MHz		66 MHz			
			Min.	Max.	Min.	Max.	Min.	Max.		
1	CLKOUT period	T_C	24.4	—	17.5	—	14.9	—	ns	Signals are measured at 50% V_{DDE}.
2	CLKOUT duty cycle	t_{CDC}	45%	55%	45%	55%	45%	55%	T_C	
3	CLKOUT rise time	t_{CRT}	—	—[4]	—	—[4]	—	—[4]	ns	
4	CLKOUT fall time	t_{CFT}	—	—[4]	—	—[4]	—	—[4]	ns	
5	CLKOUT positive edge to output signal *invalid* or Hi-Z (hold time) External bus interface CS[0:3] ADDR[8:31] DATA[0:31] BDIP OE RD_WR TA TEA TS WE/BE[0:3]	t_{COH}	1.0[5] 1.5	—	1.0[5] 1.5	—	1.0[5] 1.5	—	ns	EBTS = 0 EBTS = 1 Hold time selectable via SIU_ECCR [EBTS] bit.
	CLKOUT positive edge to output signal *invalid* or Hi-Z (hold time) Calibration bus interface CAL_CS[0, 2:3] CAL_ADDR[10:30] CAL_DATA[0:15] CAL_OE CAL_RD_WR CAL_TS CAL_WE/BE[0:1]	t_{CCOH}	1.0[5] 1.5	—	1.0[5] 1.5	—	1.0[5] 1.5	—	ns	EBTS = 0 EBTS = 1 Hold time selectable via SIU_ECCR [EBTS] bit.

Table 22. Bus Operation Timing[1] (continued)

Spec	Characteristic and Description	Symbol	External Bus Frequency [2, 3]						Unit	Notes
			40 MHz		56 MHz		66 MHz			
			Min.	Max.	Min.	Max.	Min.	Max.		
6	CLKOUT positive edge to output signal *valid* (output delay) External bus interface CS[0:3] ADDR[8:31] DATA[0:31] BDIP OE RD_WR TA TEA TS WE/BE[0:3]	t_{COV}	—	10.0[5] 11.0	—	7.5[5] 8.5	—	6.0[5] 7.0	ns	EBTS = 0 EBTS = 1 Output valid time selectable via SIU_ECCR [EBTS] bit.
6a	CLKOUT positive edge to output signal valid (output delay) Calibration bus interface CAL_CS[0, 2:3] CAL_ADDR[10:30] CAL_DATA[0:15] CAL_OE CAL_RD_WR CAL_TS CAL_WE/BE[0:1]	t_{CCOV}	—	11.0[5] 12.0	—	8.5[5] 9.5	—	7.0[5] 8.0	ns	EBTS = 0 EBTS = 1 Output valid time selectable via SIU_ECCR [EBTS] bit.
7	Input signal *valid* to CLKOUT positive edge (setup time) External bus interface ADDR[8:31] DATA[0:31] RD_WR TA TEA TS	t_{CIS}	10.0	—	7.0	—	5.0	—	ns	
	Input signal valid to CLKOUT positive edge (setup time) Calibration bus interface CAL_ADDR[10:30] CAL_DATA[0:15] CAL_RD_WR CAL_TS	t_{CCIS}	11.0	—	8.0	—	6.0	—	ns	

Table 22. Bus Operation Timing[1] (continued)

Spec	Characteristic and Description	Symbol	External Bus Frequency [2, 3]						Unit	Notes
			40 MHz		56 MHz		66 MHz			
			Min.	Max.	Min.	Max.	Min.	Max.		
8	CLKOUT positive edge to input signal *invalid* (hold time) External bus interface ADDR[8:31] DATA[0:31] RD_WR TA TEA TS	t_{CIH}	1.0	—	1.0	—	1.0	—	ns	
	CLKOUT positive edge to input signal *invalid* (hold time) Calibration bus interface CAL_ADDR[10:30] CAL_DATA[0:15] CAL_RD_WR CAL_TS	t_{CCIH}	1.0	—	1.0	—	1.0	—	ns	

1 EBI timing specified at: V_{DDE} = 1.6–3.6 V (unless stated otherwise); $T_A = T_L$ to T_H; and CL = 30 pF with DSC = 0b10.

2 Speed is the nominal maximum frequency. Max. speed is the maximum speed allowed including frequency modulation (FM). 82 MHz parts allow for 80 MHz system clock + 2% FM; 114 MHz parts allow for 112 MHz system clock + 2% FM; and 135 MHz parts allow for 132 MHz system clock + 2% FM.

3 The external bus is limited to half the speed of the internal bus.

4 Refer to fast pad timing in Table 17 and Table 18 (different values for 1.8 V and 3.3 V).

5 SIU_ECCR[EBTS] = 0 timings are tested and valid at V_{DDE} = 2.25–3.6 V only; SIU_ECCR[EBTS] = 1 timings are tested and valid at V_{DDE} = 1.6–3.6 V.

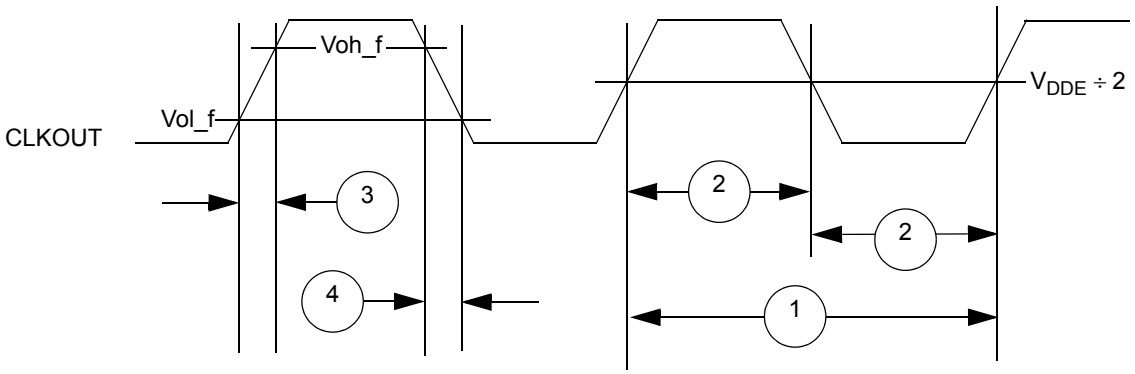


Figure 12. CLKOUT Timing

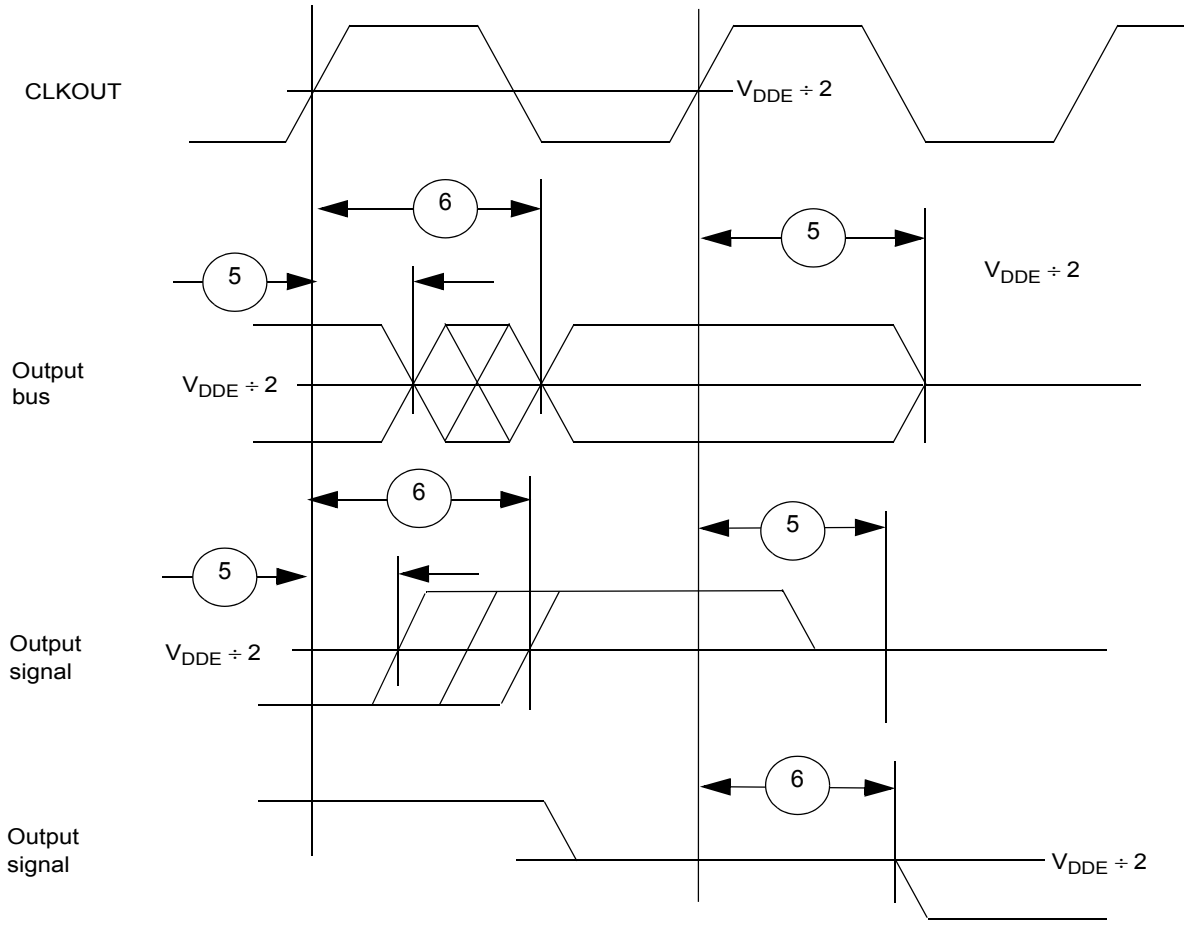


Figure 13. Synchronous Output Timing

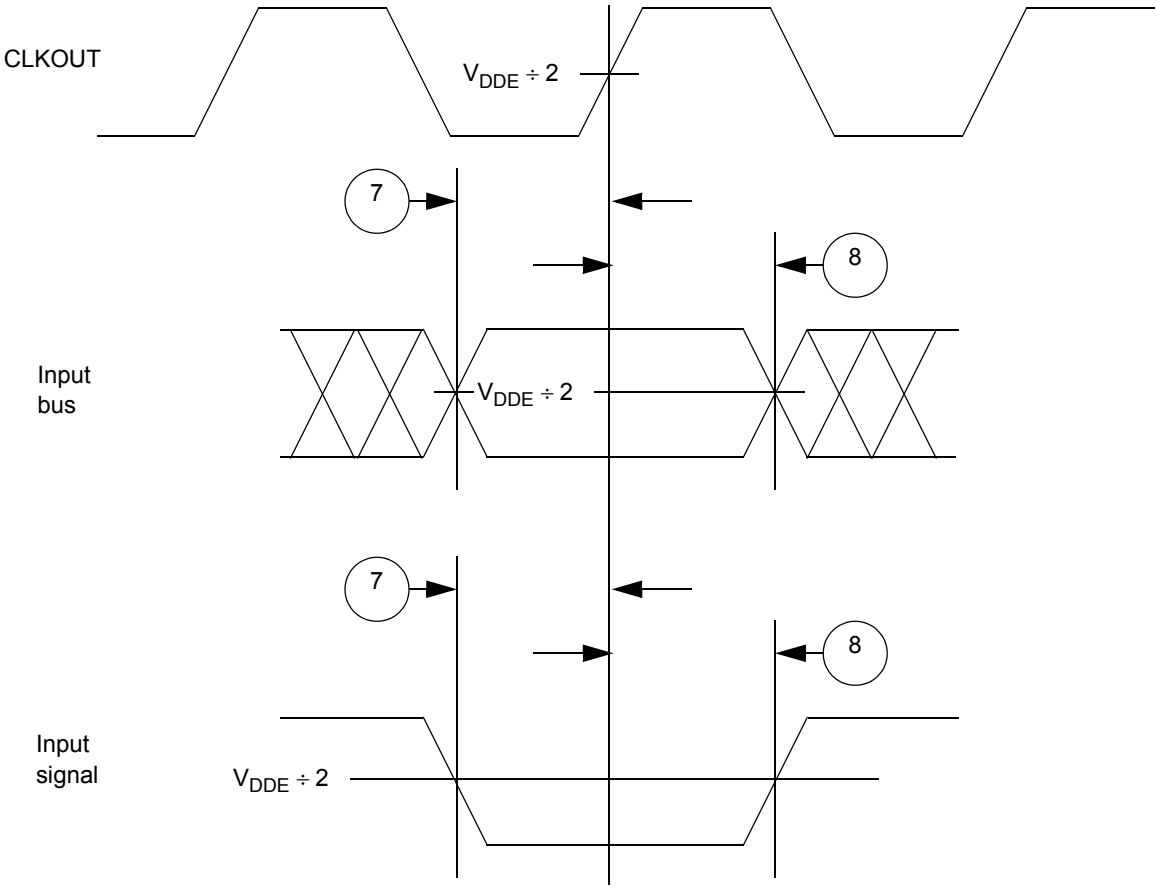


Figure 14. Synchronous Input Timing

3.13.5 External Interrupt Timing (IRQ Signals)

Table 23. External Interrupt Timing [1]

Spec	Characteristic	Symbol	Min.	Max.	Unit
1	IRQ pulse-width low	t_{IPWL}	3	—	t_{CYC}
2	IRQ pulse-width high	T_{IPWH}	3	—	t_{CYC}
3	IRQ edge-to-edge time [2]	t_{ICYC}	6	—	t_{CYC}

1 IRQ timing specified at: V_{DDEH} = 3.0–5.25 V and $T_A = T_L$ to T_H.

2 Applies when IRQ signals are configured for rising-edge or falling-edge events, but not both.

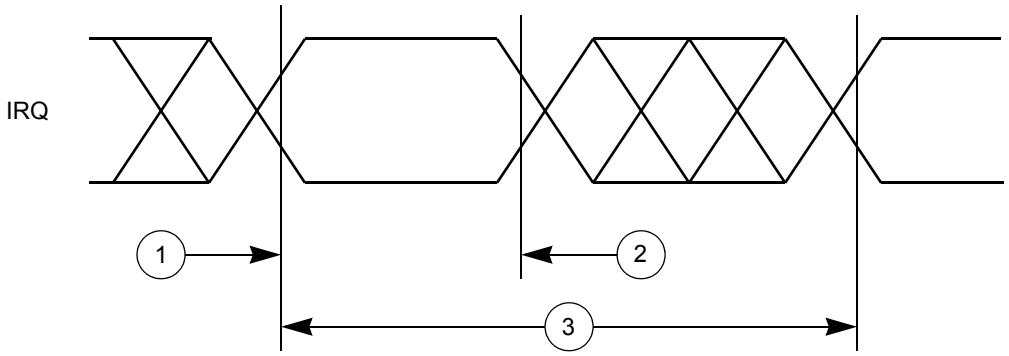


Figure 15. External Interrupt Timing

3.13.6 eTPU Timing

Table 24. eTPU Timing [1]

Spec	Characteristic	Symbol	Min.	Max	Unit
1	eTPU input channel pulse width	t_{ICPW}	4	—	t_{CYC}
2	eTPU output channel pulse width	t_{OCPW}	2 [2]	—	t_{CYC}

1 eTPU timing specified at: V_{DDEH} = 3.0–5.25 V and $T_A = T_L$ to T_H.

2 This specification does not include the rise and fall times. When calculating the minimum eTPU pulse width, include the rise and fall times defined in the slew rate control fields (SRC) of the pad configuration registers (PCR).

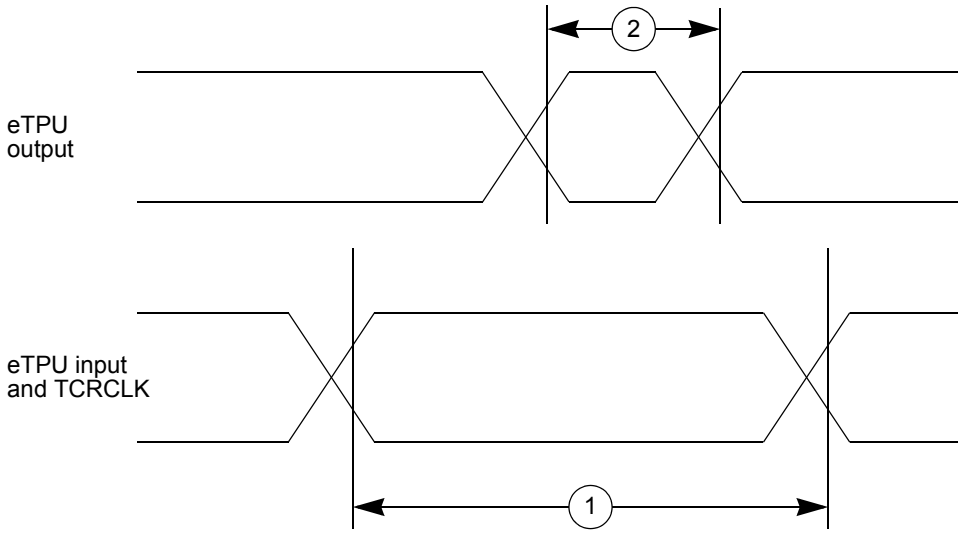


Figure 16. eTPU Timing

3.13.7 eMIOS Timing

Table 25. eMIOS Timing [1]

Spec	Characteristic	Symbol	Min.	Max.	Unit
1	eMIOS input pulse width	t_{MIPW}	4	—	t_{CYC}
2	eMIOS output pulse width	t_{MOPW}	1 [2]	—	t_{CYC}

1 eMIOS timing specified at: V_{DDEH} = 3.0–5.25 V and $T_A = T_L$ to T_H.

2 This specification does not include the rise and fall times. When calculating the minimum eMIOS pulse width, include the rise and fall times defined in the slew rate control field (SRC) in the pad configuration register (PCR).

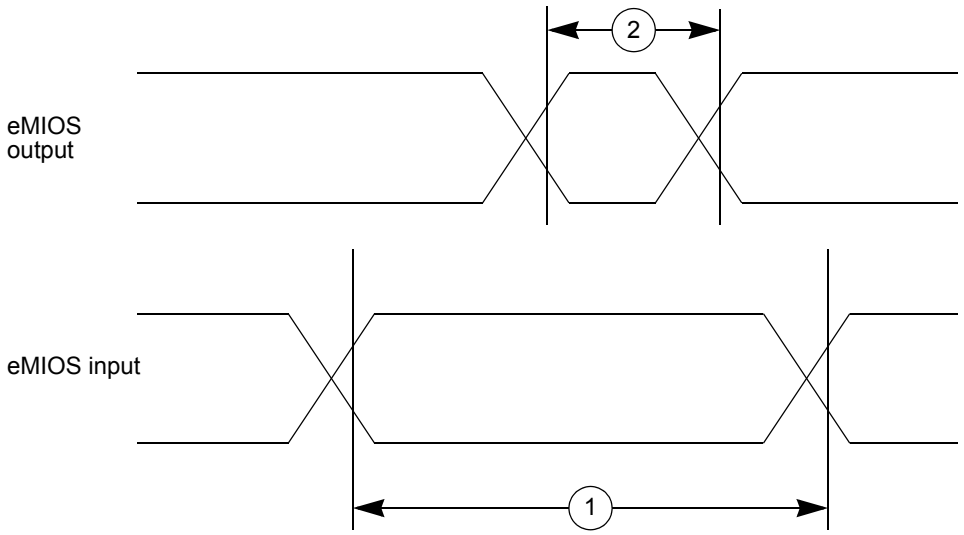


Figure 17. eMIOS Timing

3.13.8 DSPI Timing

Table 26. DSPI Timing[1, 2]

Spec	Characteristic	Symbol	80 MHz		112 MHz		132 MHz		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	
1	SCK cycle time[3, 4]	t_{SCK}	24.4 ns	2.9 ms	17.5 ns	2.1 ms	14.8 ns	1.8 ms	—
2	PCS to SCK delay[5]	t_{CSC}	23	—	15	—	13	—	ns
3	After SCK delay[6]	t_{ASC}	22	—	14	—	12	—	ns
4	SCK duty cycle	t_{SDC}	(t_{SCK} ÷ 2) – 2 ns	(t_{SCK} ÷ 2) + 2 ns	(t_{SCK} ÷ 2) – 2 ns	(t_{SCK} ÷ 2) + 2 ns	(t_{SCK} ÷ 2) – 2 ns	(t_{SCK} ÷ 2) + 2 ns	ns
5	Slave access time ($\overline{SS}$ active to SOUT driven)	t_A	—	25	—	25	—	25	ns
6	Slave SOUT disable time ($\overline{SS}$ inactive to SOUT Hi-Z, or invalid)	t_{DIS}	—	25	—	25	—	25	ns
7	PCS*x* to $\overline{PCSS}$ time	t_{PCSC}	4	—	4	—	4	—	ns
8	$\overline{PCSS}$ to PCS*x* time	t_{PASC}	5	—	5	—	5	—	ns

Table 26. DSPI Timing[1, 2] (continued)

Spec	Characteristic	Symbol	80 MHz		112 MHz		132 MHz		Unit
			Min.	Max.	Min.	Max.	Min.	Max.	
9	Data setup time for inputs Master (MTFE = 0) Slave Master (MTFE = 1, CPHA = 0)[7] Master (MTFE = 1, CPHA = 1)	t_{SUI}	 20 2 –4 20	 — — — —	 20 2 3 20	 — — — —	 20 2 6 20	 — — — —	 ns ns ns ns
10	Data hold time for inputs Master (MTFE = 0) Slave Master (MTFE = 1, CPHA = 0)[7] Master (MTFE = 1, CPHA = 1)	t_{HI}	 –4 7 21 –4	 — — — —	 –4 7 14 –4	 — — — —	 –4 7 12 –4	 — — — —	 ns ns ns ns
11	Data valid (after SCK edge) Master (MTFE = 0) Slave Master (MTFE = 1, CPHA = 0) Master (MTFE = 1, CPHA = 1)	t_{SUO}	 — — — —	 5 25 18 5	 — — — —	 5 25 14 5	 — — — —	 5 25 13 5	 ns ns ns ns
12	Data hold time for outputs Master (MTFE = 0) Slave Master (MTFE = 1, CPHA = 0) Master (MTFE = 1, CPHA = 1)	t_{HO}	 –5 5.5 8 –5	 — — — —	 –5 5.5 4 –5	 — — — —	 –5 5.5 3 –5	 — — — —	 ns ns ns ns

1 All DSPI timing specifications use the fastest slew rate (SRC = 0b11) on pad type M or MH. DSPI signals using pad types of S or SH have an additional delay based on the slew rate. DSPI timing is specified at: V_{DDEH} = 3.0–5.25 V;T_A = T_L to T_H; and CL = 50 pF with SRC = 0b11.

2 Speed is the nominal maximum frequency. Max. speed is the maximum speed allowed including frequency modulation (FM). 82 MHz parts allow for 80 MHz system clock + 2% FM; 114 MHz parts allow for 112 MHz system clock + 2% FM; and 135 MHz parts allow for 132 MHz system clock + 2% FM.

3 The minimum SCK cycle time restricts the baud rate selection for the given system clock rate. These numbers are calculated based on two MPC55xx devices communicating over a DSPI link.

4 The actual minimum SCK cycle time is limited by pad performance.

5 The maximum value is programmable in DSPI_CTARx[PSSCK] and DSPI_CTARx[CSSCK].

6 The maximum value is programmable in DSPI_CTARx[PASC] and DSPI_CTARx[ASC].

7 This number is calculated using the SMPL_PT field in DSPI_MCR set to 0b10.

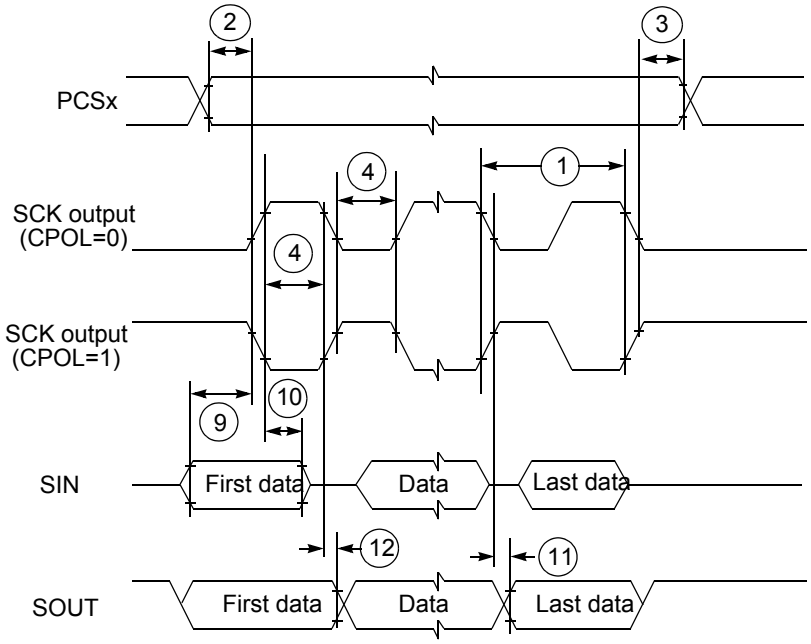


Figure 18. DSPI Classic SPI Timing—Master, CPHA = 0

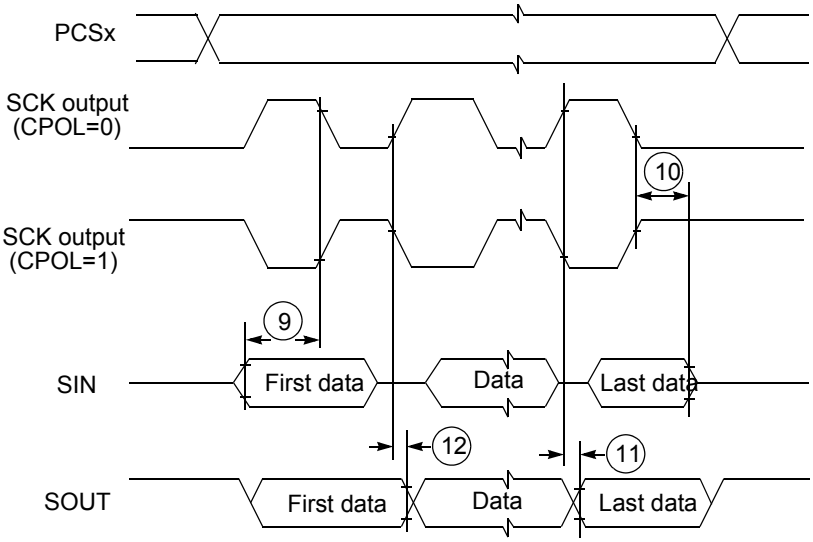


Figure 19. DSPI Classic SPI Timing—Master, CPHA = 1

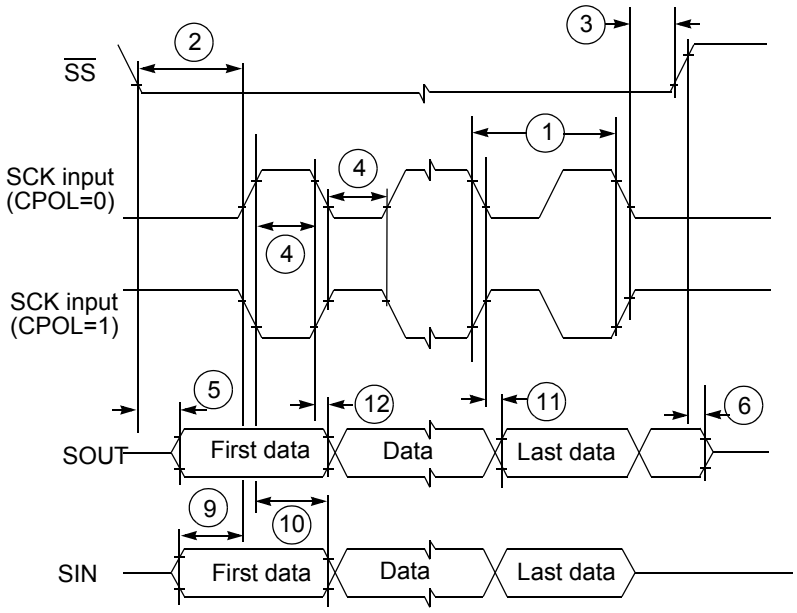


Figure 20. DSPI Classic SPI Timing—Slave, CPHA = 0

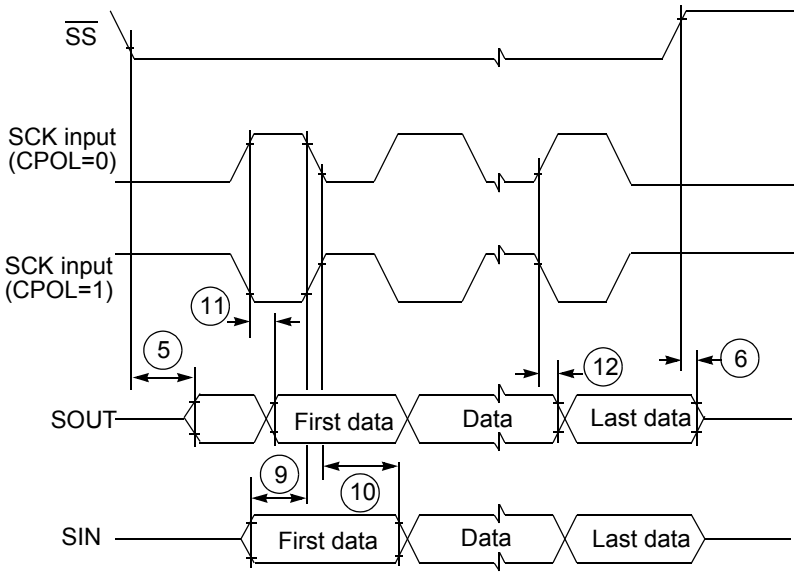


Figure 21. DSPI Classic SPI Timing—Slave, CPHA = 1

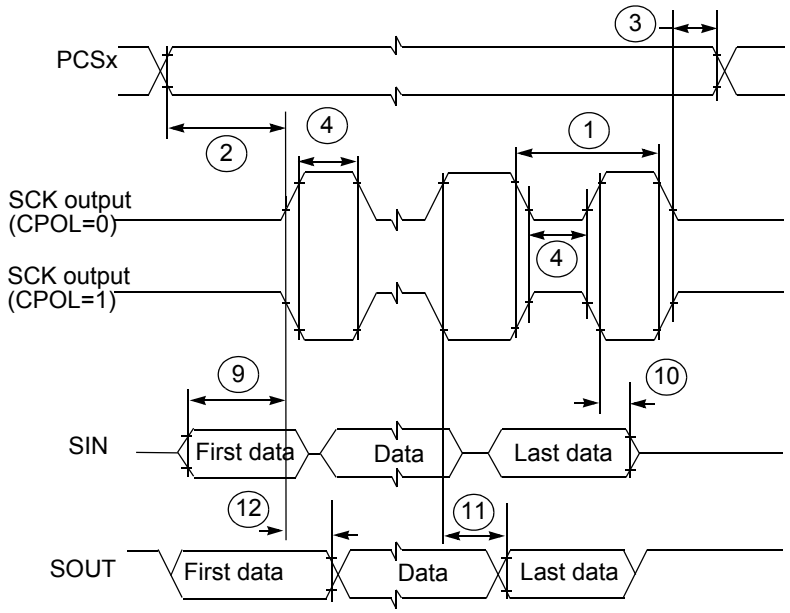


Figure 22. DSPI Modified Transfer Format Timing—Master, CPHA = 0

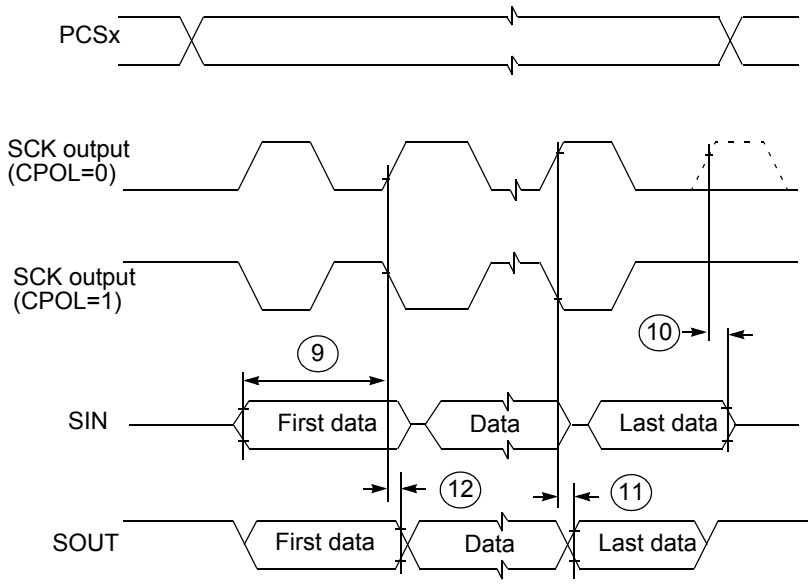


Figure 23. DSPI Modified Transfer Format Timing—Master, CPHA = 1

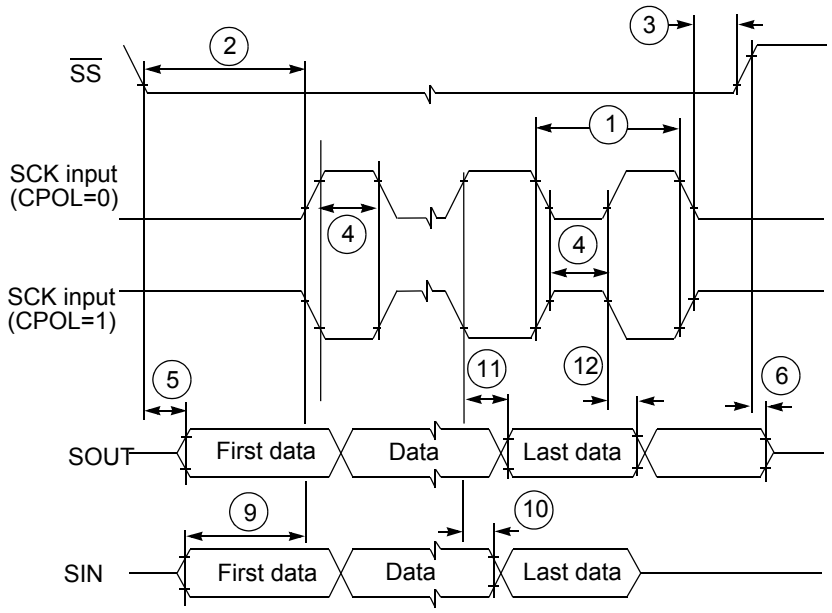


Figure 24. DSPI Modified Transfer Format Timing—Slave, CPHA = 0

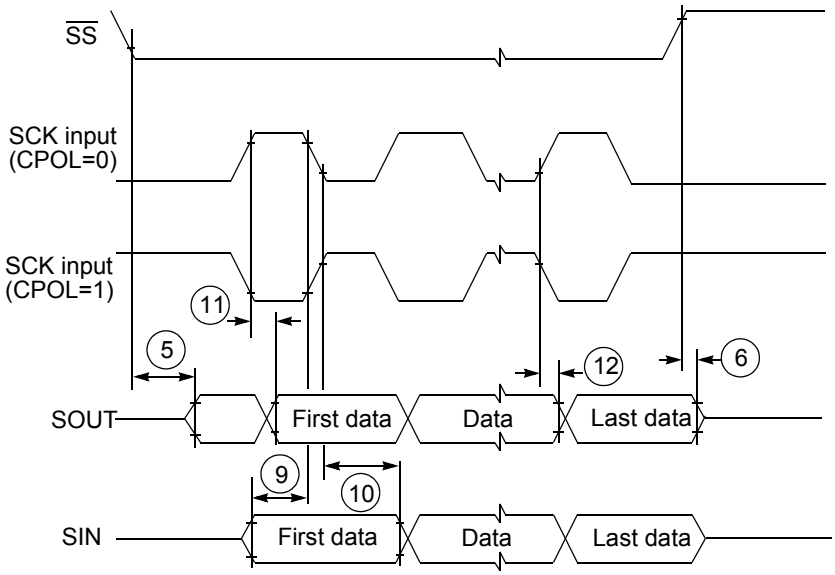


Figure 25. DSPI Modified Transfer Format Timing—Slave, CPHA = 1

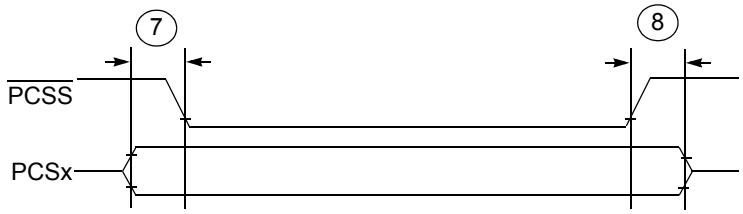


Figure 26. DSPI PCS Strobe ($\overline{\text{PCSS}}$) Timing

3.13.9 eQADC SSI Timing

Table 27. EQADC SSI Timing Characteristics

Spec	Rating	Symbol	Minimum	Typical	Maximum	Unit
2	FCK period ($t_{FCK} = 1 \div f_{FCK}$) [1, 2]	t_{FCK}	2	—	17	t_{SYS_CLK}
3	Clock (FCK) high time	t_{FCKHT}	$t_{SYS_CLK} - 6.5$	—	$9 \times (t_{SYS_CLK} + 6.5)$	ns
4	Clock (FCK) low time	t_{FCKLT}	$t_{SYS_CLK} - 6.5$	—	$8 \times (t_{SYS_CLK} + 6.5)$	ns
5	SDS lead / lag time	t_{SDS_LL}	–7.5	—	+7.5	ns
6	SDO lead / lag time	t_{SDO_LL}	–7.5	—	+7.5	ns
7	EQADC data setup time (inputs)	t_{EQ_SU}	22	—	—	ns
8	EQADC data hold time (inputs)	t_{EQ_HO}	1	—	—	ns

1 $\overline{SS}$ timing specified at V_{DDEH} = 3.0–5.25 V, $T_A = T_L$ to T_H, and CL = 25 pF with SRC = 0b11. Maximum operating frequency varies depending on track delays, master pad delays, and slave pad delays.

2 FCK duty cycle is not 50% when it is generated through the division of the system clock by an odd number.

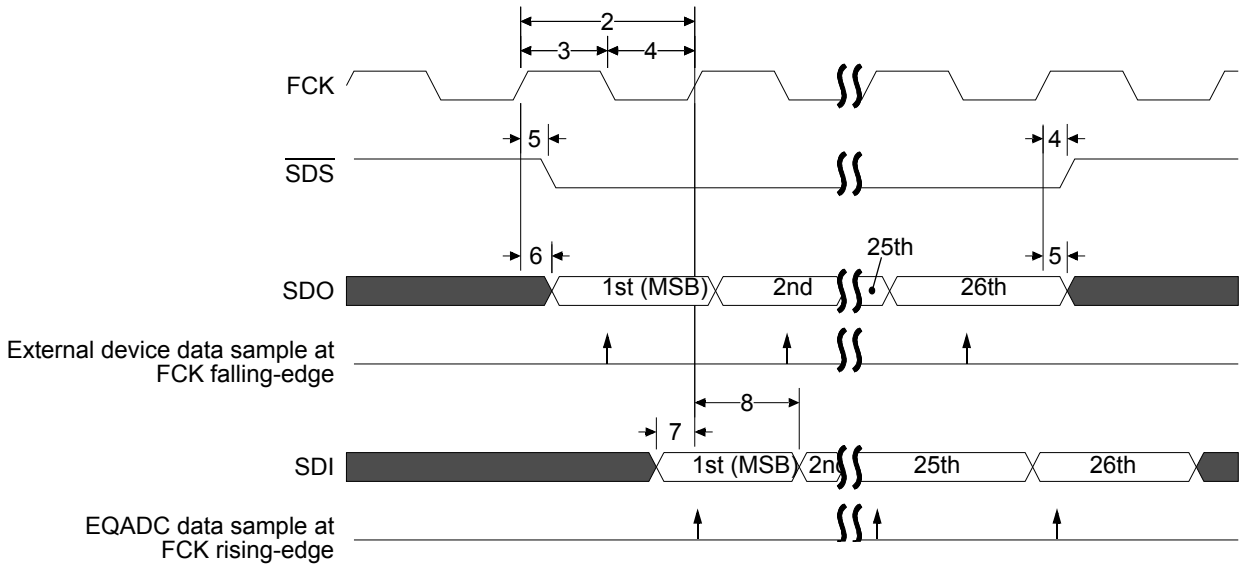


Figure 27. EQADC SSI Timing

3.14 Fast Ethernet AC Timing Specifications

Media Independent Interface (MII) Fast Ethernet Controller (FEC) signals use transistor-to-transistor logic (TTL) signal levels compatible with devices operating at 3.3 V. The timing specifications for the MII FEC signals are independent of the system clock frequency (part speed designation).

3.14.1 MII FEC Receive Signal Timing FEC_RXD[3:0], FEC_RX_DV, FEC_RX_ER, and FEC_RX_CLK

The receive functions correctly up to an FEC_RX_CLK maximum frequency of 25 MHz plus one percent. There is no minimum frequency requirement. The processor clock frequency must exceed four times the FEC_RX_CLK frequency.

Table 28 lists MII FEC receive channel timings.

Table 28. MII FEC Receive Signal Timing

Spec	Characteristic	Min.	Max	Unit
1	FEC_RXD[3:0], FEC_RX_DV, FEC_RX_ER to FEC_RX_CLK setup	5	—	ns
2	FEC_RX_CLK to FEC_RXD[3:0], FEC_RX_DV, FEC_RX_ER hold	5	—	ns
3	FEC_RX_CLK pulse-width high	35%	65%	FEC_RX_CLK period
4	FEC_RX_CLK pulse-width low	35%	65%	FEC_RX_CLK period

Figure 28 shows MII FEC receive signal timings listed in Table 28.

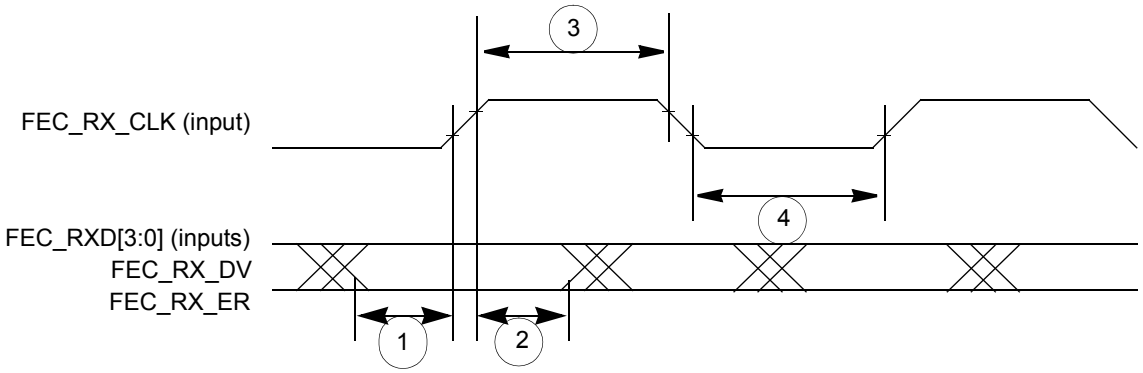


Figure 28. MII FEC Receive Signal Timing Diagram

3.14.2 MII FEC Transmit Signal Timing FEC_TXD[3:0], FEC_TX_EN, FEC_TX_ER, FEC_TX_CLK

The transmitter functions correctly up to the FEC_TX_CLK maximum frequency of 25 MHz plus one percent. There is no minimum frequency requirement. In addition, the processor clock frequency must exceed twice the FEC_TX_CLK frequency.

The transmit outputs (FEC_TXD[3:0], FEC_TX_EN, FEC_TX_ER) can be programmed to transition from either the rising- or falling-edge of TX_CLK, and the timing is the same in either case. These options allow the use of non-compliant MII PHYs.

Refer to the Fast Ethernet Controller (FEC) chapter of the device reference manual for details of this option and how to enable it.

Table 29 lists MII FEC transmit channel timings.

Table 29. MII FEC Transmit Signal Timing

Spec	Characteristic	Min.	Max	Unit
5	FEC_TX_CLK to FEC_TXD[3:0], FEC_TX_EN, FEC_TX_ER invalid	5	—	ns
6	FEC_TX_CLK to FEC_TXD[3:0], FEC_TX_EN, FEC_TX_ER valid	—	25	ns
7	FEC_TX_CLK pulse-width high	35%	65%	FEC_TX_CLK period
8	FEC_TX_CLK pulse-width low	35%	65%	FEC_TX_CLK period

Figure 29 shows MII FEC transmit signal timings listed in Table 29.

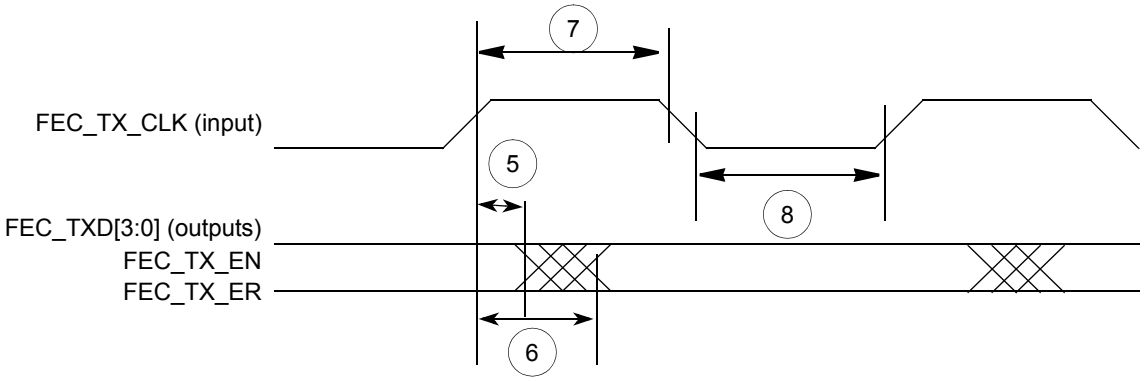


Figure 29. MII FEC Transmit Signal Timing Diagram

3.14.3 MII FEC Asynchronous Inputs Signal Timing FEC_CRS and FEC_COL

Table 30 lists MII FEC asynchronous input signal timing.

Table 30. MII FEC Asynchronous Inputs Signal Timing

Spec	Characteristic	Min.	Max	Unit
9	FEC_CRS, FEC_COL minimum pulse width	1.5	—	FEC_TX_CLK period

Figure 30 shows MII FEC asynchronous input timing listed in Table 30.

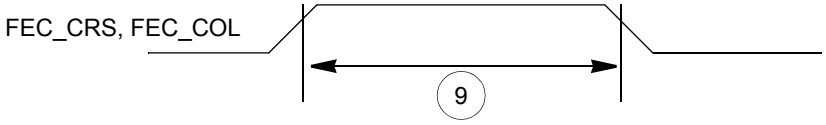


Figure 30. MII FEC Asynchronous Inputs Timing Diagram

3.14.4 MII FEC Serial Management Channel Timing FEC_MDIO and FEC_MDC

Table 31 lists MII FEC serial management channel timing. The FEC functions correctly with a maximum FEC_MDC frequency of 2.5 MHz.

Table 31. MII FEC Serial Management Channel Timing

Spec	Characteristic	Min.	Max	Unit
10	FEC_MDC falling-edge to FEC_MDIO output invalid (minimum propagation delay)	0	—	ns
11	FEC_MDC falling-edge to FEC_MDIO output valid (maximum propagation delay)	—	25	ns
12	FEC_MDIO (input) to FEC_MDC rising-edge setup	10	—	ns
13	FEC_MDIO (input) to FEC_MDC rising-edge hold	0	—	ns
14	FEC_MDC pulse-width high	40%	60%	FEC_MDC period
15	FEC_MDC pulse-width low	40%	60%	FEC_MDC period

Figure 31 shows MII FEC serial management channel timing listed in Table 31.

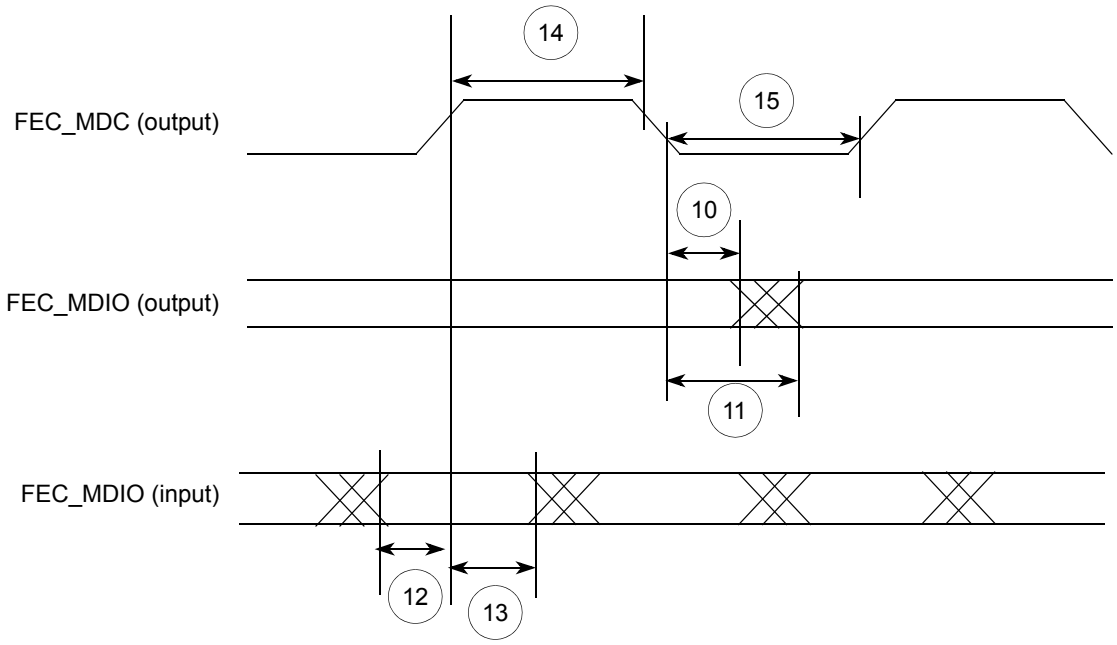


Figure 31. MII FEC Serial Management Channel Timing Diagram

4 Mechanicals

4.1 MPC5567 324 PBGA Pinouts

Figure 32 is a pinout for the MPC5567 324 PBGA package.

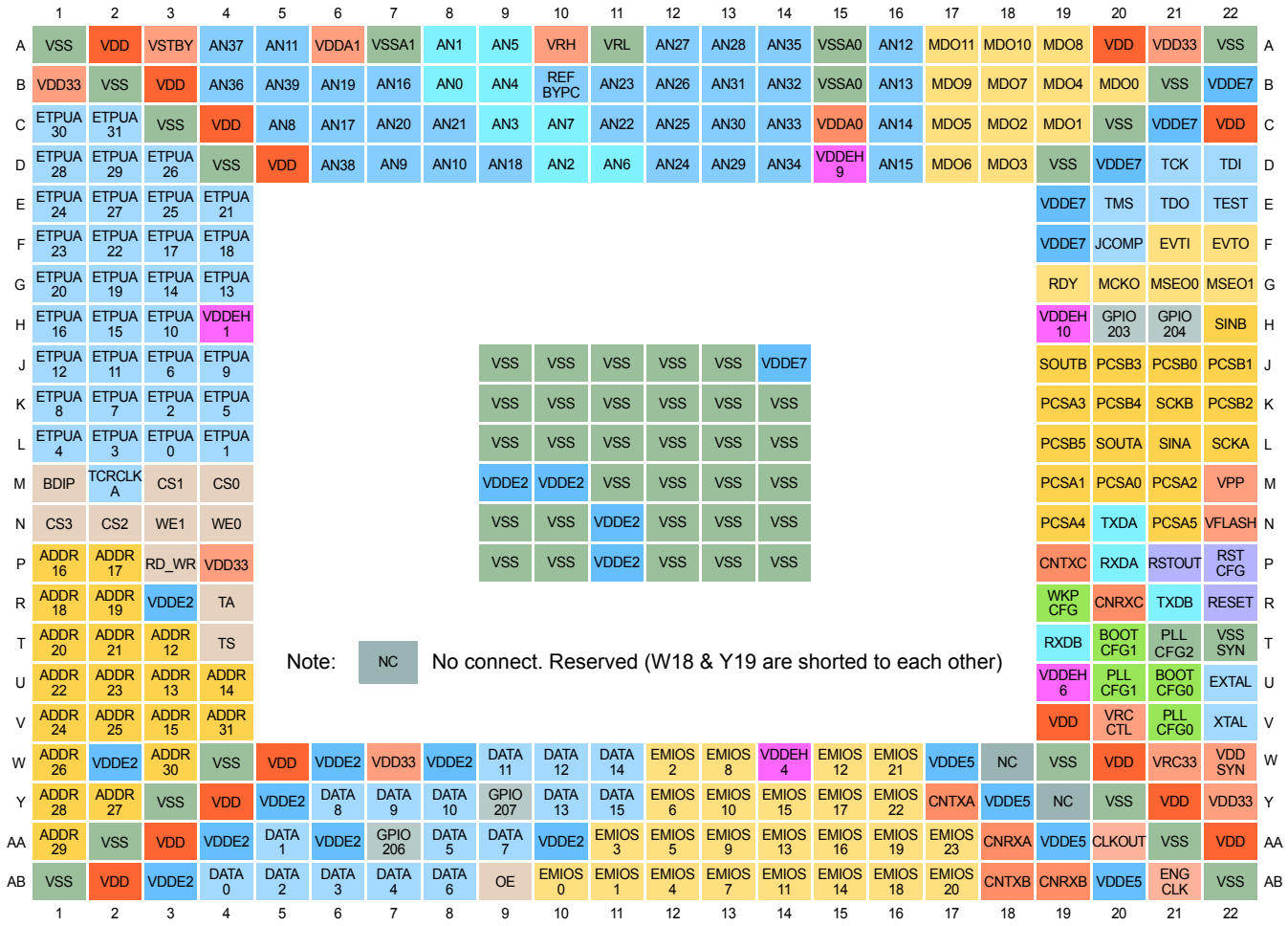


Figure 32. MPC5567 324 Package

4.2 MPC5567 416 PBGA Pinout

Figure 33, Figure 34, and Figure 35 show the pinout for the MPC5567 416 PBGA package. The alternate Fast Ethernet Controller (FEC) signals are multiplexed with the data calibration bus signals.

NOTE

The MPC5500 devices are pin compatible for software portability and use the primary function names to label the pins in the BGA diagram. Although some devices do not support all the primary functions shown in the BGA diagram, the muxed and GPIO signals on those pins remain available. See the signals chapter in the device reference manual for the signal muxing.

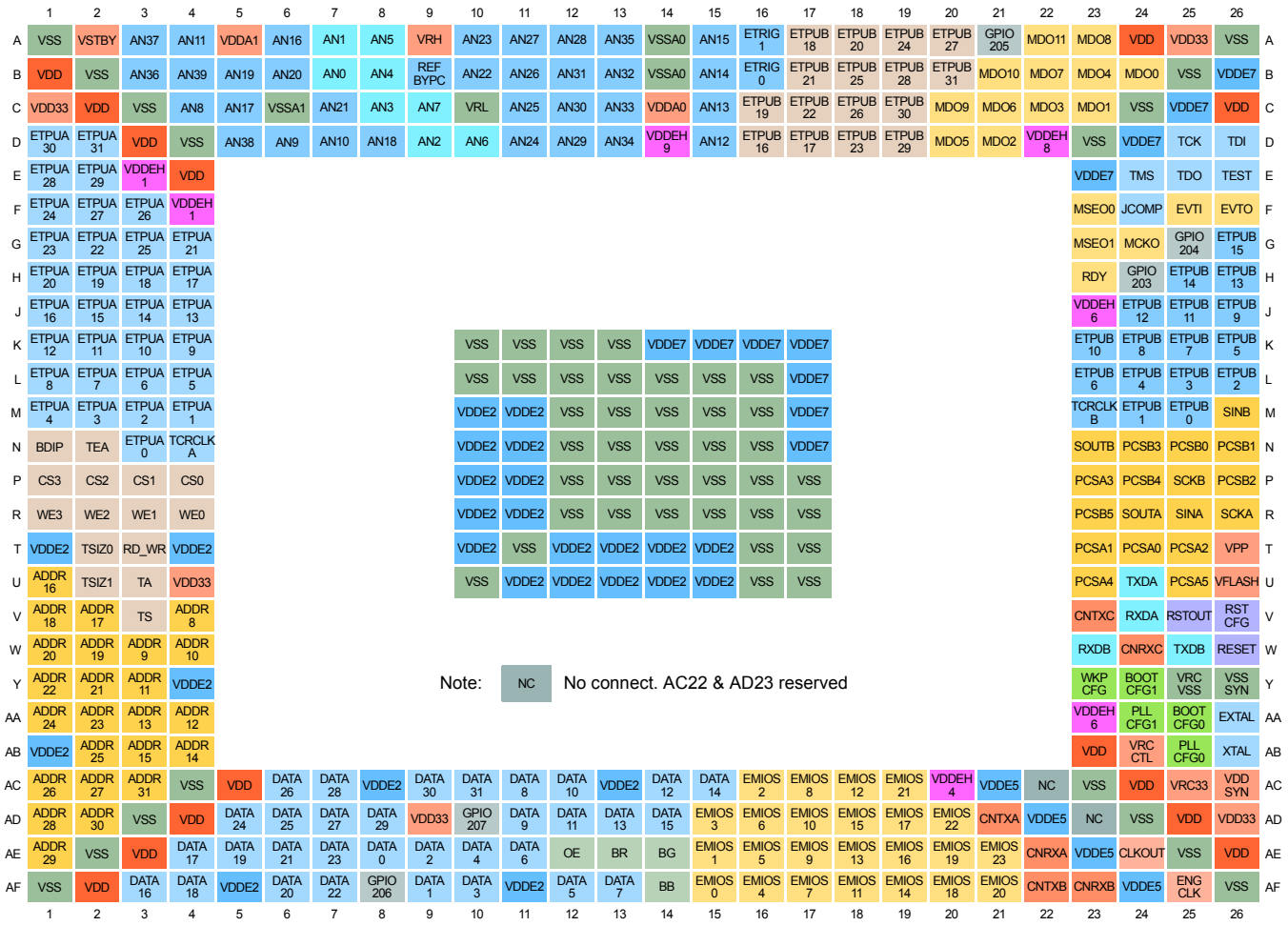
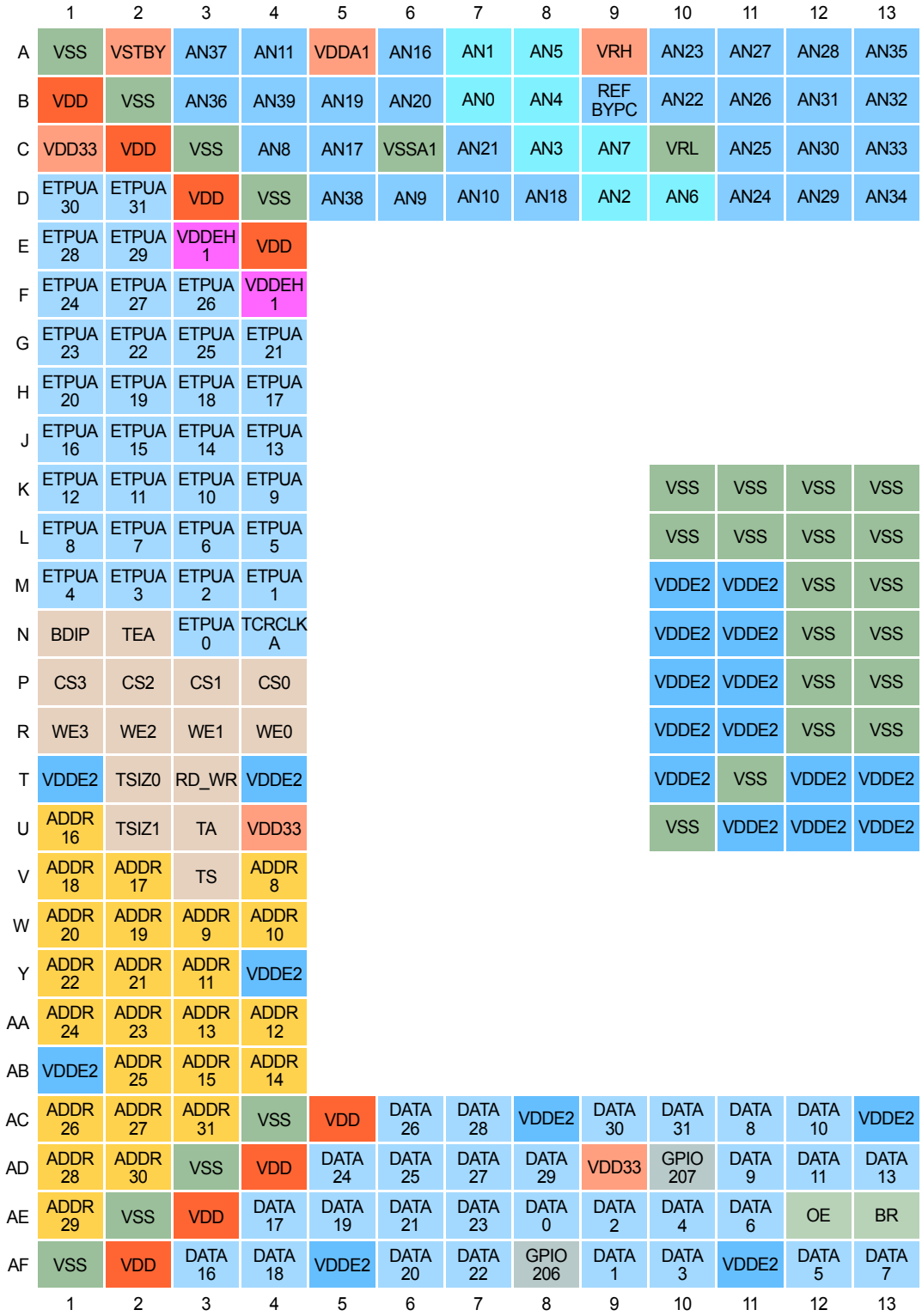


Figure 33. MPC5567 416 Package



	1	2	3	4	5	6	7	8	9	10	11	12	13
A	VSS	VSTBY	AN37	AN11	VDDA1	AN16	AN1	AN5	VRH	AN23	AN27	AN28	AN35
B	VDD	VSS	AN36	AN39	AN19	AN20	AN0	AN4	REF BYPC	AN22	AN26	AN31	AN32
C	VDD33	VDD	VSS	AN8	AN17	VSSA1	AN21	AN3	AN7	VRL	AN25	AN30	AN33
D	ETPUA 30	ETPUA 31	VDD	VSS	AN38	AN9	AN10	AN18	AN2	AN6	AN24	AN29	AN34
E	ETPUA 28	ETPUA 29	VDDEH 1	VDD									
F	ETPUA 24	ETPUA 27	ETPUA 26	VDDEH 1									
G	ETPUA 23	ETPUA 22	ETPUA 25	ETPUA 21									
H	ETPUA 20	ETPUA 19	ETPUA 18	ETPUA 17									
J	ETPUA 16	ETPUA 15	ETPUA 14	ETPUA 13									
K	ETPUA 12	ETPUA 11	ETPUA 10	ETPUA 9						VSS	VSS	VSS	VSS
L	ETPUA 8	ETPUA 7	ETPUA 6	ETPUA 5						VSS	VSS	VSS	VSS
M	ETPUA 4	ETPUA 3	ETPUA 2	ETPUA 1						VDDE2	VDDE2	VSS	VSS
N	BDIP	TEA	ETPUA 0	TCRCLK A						VDDE2	VDDE2	VSS	VSS
P	CS3	CS2	CS1	CS0						VDDE2	VDDE2	VSS	VSS
R	WE3	WE2	WE1	WE0						VDDE2	VDDE2	VSS	VSS
T	VDDE2	TSIZ0	RD_WR	VDDE2						VDDE2	VSS	VDDE2	VDDE2
U	ADDR 16	TSIZ1	TA	VDD33						VSS	VDDE2	VDDE2	VDDE2
V	ADDR 18	ADDR 17	TS	ADDR 8									
W	ADDR 20	ADDR 19	ADDR 9	ADDR 10									
Y	ADDR 22	ADDR 21	ADDR 11	VDDE2									
AA	ADDR 24	ADDR 23	ADDR 13	ADDR 12									
AB	VDDE2	ADDR 25	ADDR 15	ADDR 14									
AC	ADDR 26	ADDR 27	ADDR 31	VSS	VDD	DATA 26	DATA 28	VDDE2	DATA 30	DATA 31	DATA 8	DATA 10	VDDE2
AD	ADDR 28	ADDR 30	VSS	VDD	DATA 24	DATA 25	DATA 27	DATA 29	VDD33	GPIO 207	DATA 9	DATA 11	DATA 13
AE	ADDR 29	VSS	VDD	DATA 17	DATA 19	DATA 21	DATA 23	DATA 0	DATA 2	DATA 4	DATA 6	OE	BR
AF	VSS	VDD	DATA 16	DATA 18	VDDE2	DATA 20	DATA 22	GPIO 206	DATA 1	DATA 3	VDDE2	DATA 5	DATA 7
	1	2	3	4	5	6	7	8	9	10	11	12	13

Figure 34. MPC5567 416 Package Left Side (view 1 of 2)

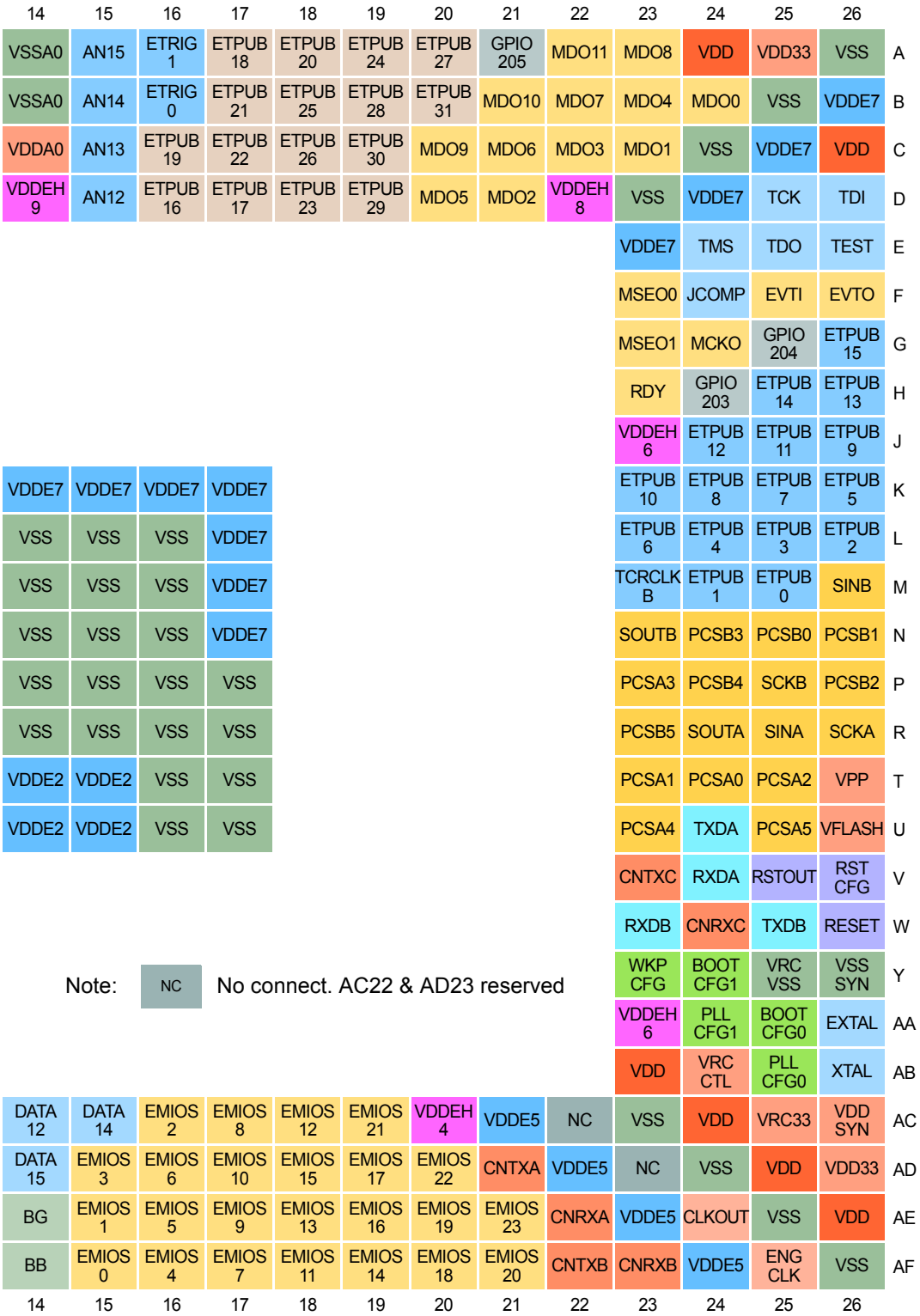


Figure 35. MPC5567 416 Package Right Side (view 2 of 2)

Figure 36. MPC5567 416 Package

4.3 MPC5567 324-Pin Package Dimensions

The package drawings of the MPC5567 324-pin TEPBGA package are shown in Figure 37.

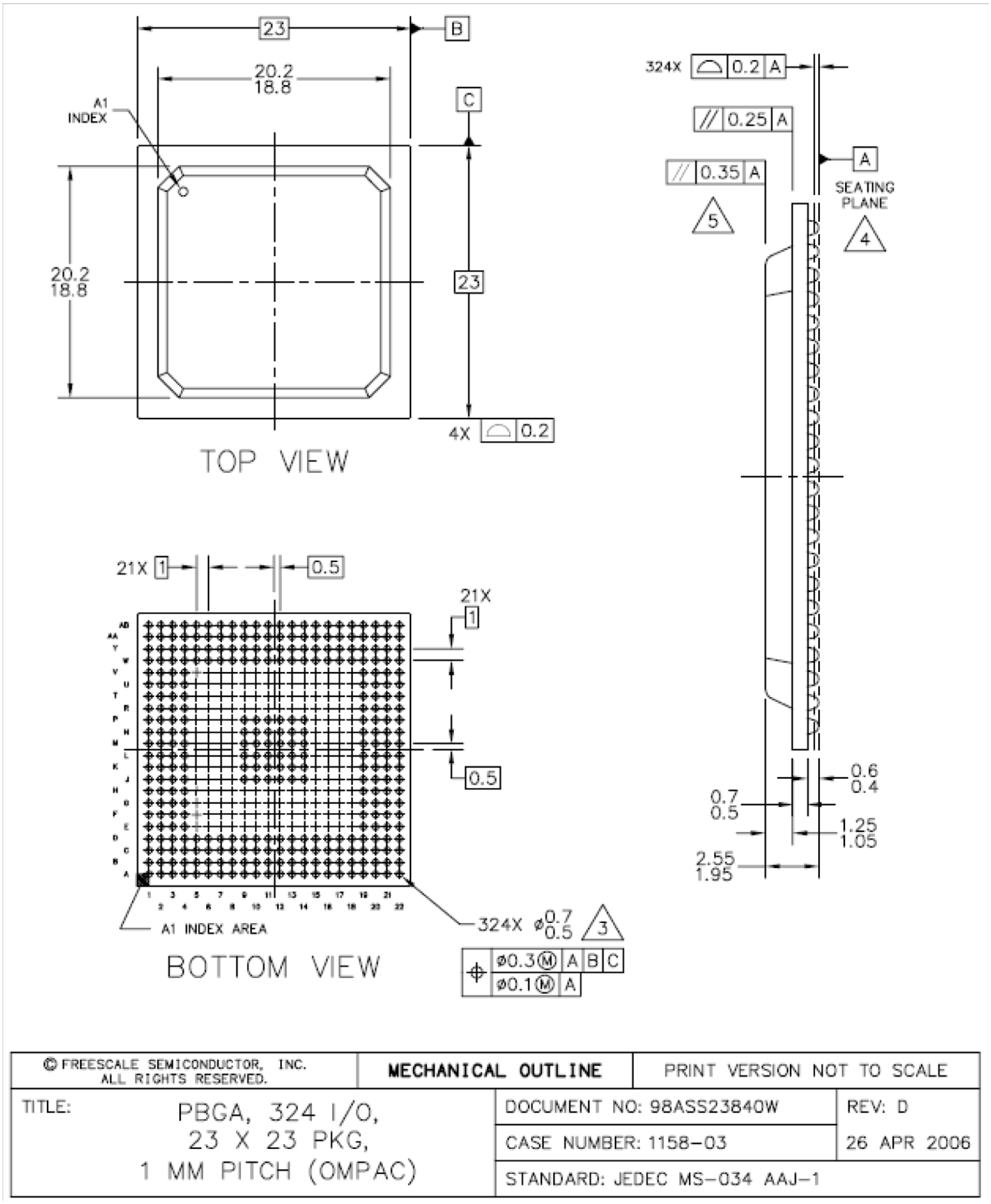


Figure 37. MPC5567 324 TEPBGA Package

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

© FREESCALE SEMICONDUCTOR, INC.
ALL RIGHTS RESERVED.

MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE

TITLE:	DOCUMENT NO: 98ASS23840W	REV: D
PBGA, 324 I/O, 23 X 23 PKG, 1 MM PITCH (OMPAC)	CASE NUMBER: 1158–03	26 APR 2006
	STANDARD: JEDEC MS–034 AAJ–1	

Figure 37. MPC5567 324 TEPBGA Package (continued)

4.4 MPC5567 416-Pin Package Dimensions

The package drawings of the MPC5567 416 pin TEPBGA package are shown in Figure 38.

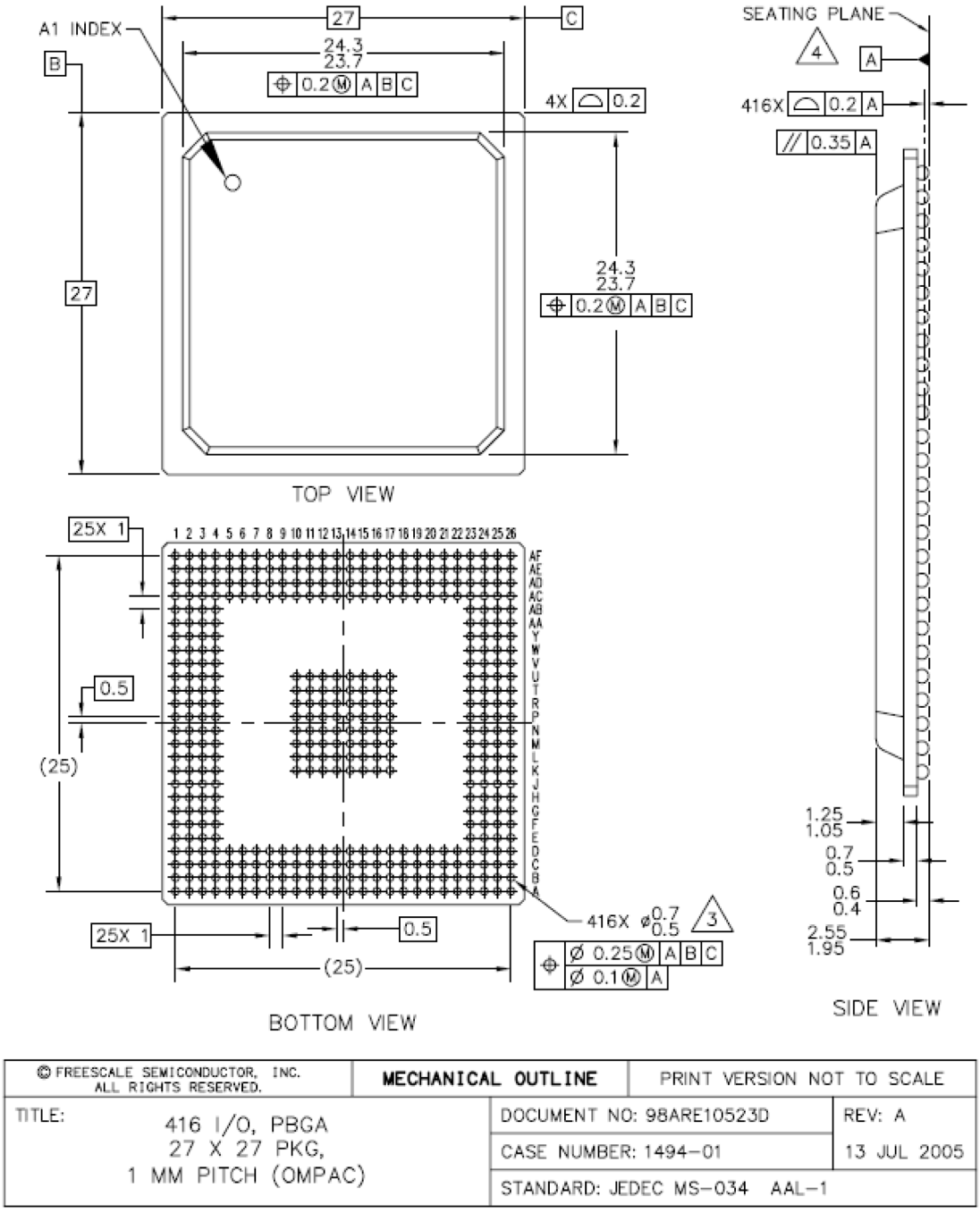


Figure 38. MPC5567 416 TEPBGA Package

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

© FREESCALE SEMICONDUCTOR, INC. ALL RIGHTS RESERVED.	MECHANICAL OUTLINE	PRINT VERSION NOT TO SCALE
TITLE: 416 I/O, PBGA 27 X 27 PKG, 1 MM PITCH (OMPAC)	DOCUMENT NO: 98ARE10523D	REV: A
	CASE NUMBER: 1494–01	13 JUL 2005
	STANDARD: JEDEC MS–034 AAL–1	

Figure 38. MPC5567 416 TEPBGA Package (continued)

5 Revision History for the MPC5567 Data Sheet

The history of revisions made to this data sheet are described in this section. The changes are divided into each revision of this document, and are listed in sequential page number order.

5.1 Information Changed Between Revisions 1.0 and 2.0

The following table lists the substantive text changes made to paragraphs.

Table 32. Information changed between Rev 1.0 and 2.0

Section 3.7, "Power-Up/Down Sequencing"	Added the following paragraph in Section 3.7, "Power-Up/Down Sequencing": "During initial power ramp-up, when V_{stby} is 0.6v or above. a typical current of 1-3mA and maximum of 4mA may be seen until VDD is applied. This current will not reoccur until V_{stby} is lowered below V_{stby} min. specification".
	Moved Figure 2 (fISTBY Worst-case Specifications) "ISTBY Worst-case Specifications" to Section 3.7, "Power-Up/Down Sequencing".
Section 3.8, "DC Electrical Specifications"	Removed the footnote "Figure 3 shows an illustration of the IDD_STBY values interpolated for these temperature values".
	Changed the footnote attached to IDD_STBY to "The current specification relates to average standby operation after SRAM has been loaded with data. For power up current see Section 3.7, "Power-Up/Down Sequencing",Figure 2 (fISTBY Worst-case Specifications)."
	In Table 9 (DC Electrical Specifications ($T_A = T_{L\ to}\ T_H$)) the Characteristic "Refer to Figure 3 for an interpolation of this data" changed to "RAM standby current".

5.2 Information Changed Between Rev. 0.0 and 1.0

The following table lists the global changes incorporated throughout the document, and substantive text changes made to paragraphs.

Table 34. Global and Text Changes Between Rev. 0.0 and 1.0

Location	Description of Change
Global Changes	

	• Starting at the third paragraph and throughout the document, replaced:
	  • kilobytes with KB
	  • megabytes with MB
	• Put overbars on the following signals: $\overline{\text{BDIP}}$, $\overline{\text{OE}}$, $\overline{\text{TA}}$, $\overline{\text{TEA}}$, $\overline{\text{TS}}$, $\overline{\text{RSTCFG}}$
	• Changed $\overline{\text{WE}}$[0:3]/$\overline{\text{BE}}$[0:3] to $\overline{\text{WE}}$/$\overline{\text{BE}}$[0:3].
	• Added the Fast Ethernet Controller (FEC) information.

Section 1, "Overview":	

Table 34. Global and Text Changes Between Rev. 0.0 and 1.0 (continued)

Location	Description of Change
	• First paragraph, text changed from ". . . based on the PowerPC Book E architecture" to ". . . built on the Power Architecture embedded technology." • Second paragraph: Changed terminology from PowerPC Book E architecture to Power Architecture terminology. • Added new fourth paragraph about VLE feature. • Added the VLE paragraph. • Added paragraph about the Fast Ethernet Controller directly after the System Integration Unit paragraph. • Added paragraph about the FlexRay Controller directly after the Fast Ethernet Controller paragraph. • Added the sentence directly preceding Table 1: 'Unless noted in this data sheet, all specifications apply from T_L to T_H.'
Sections 3.7.1, 3.7.2 and 3.7.3: Reordered sections resulting in the following order and section renumbering:	
	• Section 3.7.1, "Input Value of Pins During POR Dependent on VDD33," then • Section 3.7.2, "Power-Up Sequence (VRC33 Grounded)," then • Section 3.7.3, "Power-Down Sequence (VRC33 Grounded).
Section 3.7.1, "Input Value of Pins During POR Dependent on VDD33," changed:	
	From: 'To avoid accidentally selecting the bypass clock because PLLCFG[0:1] and $\overline{\text{RSTCFG}}$ are not treated as ones (1s) when POR negates, V_{DD33} must not lag V_{DDSYN} and the $\overline{\text{RESET}}$ pin power (V_{DDEH6}) when powering the device by more than the V_{DD33} lag specification in Table 6. V_{DD33} individually can lag either V_{DDSYN} or the $\overline{\text{RESET}}$ power pin (V_{DDEH6}) by more than the V_{DD33} lag specification. V_{DD33} can lag one of the V_{DDSYN} or V_{DDEH6} supplies, but cannot lag both by more than the V_{DD33} lag specification. This V_{DD33} lag specification only applies during power up. V_{DD33} has no lead or lag requirements when powering down.' To: 'When powering the device, V_{DD33} must not lag V_{DDSYN} and the $\overline{\text{RESET}}$ power pin (V_{DDEH6}) by more than the V_{DD33} lag specification listed in Table 6. This avoids accidentally selecting the bypass clock mode because the internal versions of PLLCFG[0:1] and $\overline{\text{RSTCFG}}$ are not powered and therefore cannot read the default state when POR negates. V_{DD33} can lag V_{DDSYN} or the $\overline{\text{RESET}}$ power pin (V_{DDEH6}), but cannot lag both by more than the V_{DD33} lag specification. This V_{DD33} lag specification only applies during power up. V_{DD33} has no lead or lag requirements when powering down.'
Section 3.7.1, "Input Value of Pins During POR Dependent on VDD33:"	
	Added the following text directly before this section and after Table 8 *Pin Status for Medium / Slow Pads During the Power-on Sequence*: 'The values in Table 7 and Table 8 do not include the effect of the weak pull devices on the output pins during power up. Before exiting the internal POR state, the voltage on the pins goes to high-impedance until POR negates. When the internal POR negates, the functional state of the signal during reset applies and the weak pull devices (up or down) are enabled as defined in the device *Reference Manual*. If V_{DD} is too low to correctly propagate the logic signals, the weak-pull devices can pull the signals to V_{DDE} and V_{DDEH}. To avoid this condition, minimize the ramp time of the V_{DD} supply to a time period less than the time required to enable the external circuitry connected to the device outputs.'
Section 3.7.3, "Power-Down Sequence (VRC33 Grounded)" Deleted the underscore in ORed_POR to become ORed POR.	

The following table describes the changes made to information in tables and figures, and is presented in sequential page number order.

Table 35. Table and Figure Changes Between Rev. 0.0 and 1.0

Location	Description of Changes
Figure 1 MPC5500 Family Part Numbers:	• Removed the 2 in the tape and reel designator in both the graphic and in the Tape and Reel Status text. • Changed Qualification Status by adding ‘, general market flow’ to the M designator, and added an ‘S’ designator with the description of ‘Fully spec. qualified, automotive flow. • Removed temperature code A for -55 C to 125 C.
Table 1 Orderable Part Numbers:	• Changed the 132 MHz maximum operating frequency to 135 MHz. • Reordered rows to group devices by lead-free package types in descending frequency order, and leaded package types. • Footnote 1 added that reads: All devices are PPC5567, rather than MPC5567 or SPC5567, until product qualifications are complete. Not all configurations are available in the PPC parts. • Footnote 2 added that reads:’ The lowest ambient operating temperature is referenced by T_L; the highest ambient operating temperature is referenced by T_H.’ • Footnote 3 added that reads: ‘Speed is the nominal maximum frequency. Max speed is the maximum speed allowed including frequency modulation (FM). 82 MHz parts allow for 80 MHz system clock + 2% FM; 114 MHz parts allow for 112 MHz system clock + 2% FM; and 135 MHz parts allow for 132 MHz system clock + 2% FM.’
Table 2 Absolute Maximum Ratings:	• Deleted Spec 3, “Flash core voltage.” • Spec 12 “DC Input Voltage”: Deleted from second line‘. . .except for eTPUB15 and SINB (DSPI_B_SIN)’ leaving V_{DDEH} powered I/O pads. Deleted third line ‘V_{DDEH} powered by I/O pads (eTPUB15 and SINB), including the min and max values of -0.3 and 6.5 respectively, and deleted old footnote 7. • Spec 12 “DC Input Voltage”: Added footnote 8 to second line “V_{DDE} powered I/O pads” that reads: ‘Internal structures hold the input voltage less than the maximum voltage on all pads powered by the V_{DDE} supplies, if the maximum injection current specification is met (s mA for all pins) and V_{DDE} is within the operating voltage specifications. • Spec 14, column 2, changed: ‘V_{SS} differential voltage’ to ‘V_{SS} to V_{SSA} differential voltage.’ • Spec 15, column 2, changed: ‘V_{DD} differential voltage’ to ‘V_{DD} to V_{DDA} differential voltage.’ • Spec 21, Added the name of the spec, ‘*V_{RC33} to V_{DDSYN} differential voltage,’* as well as the name and cross reference to Table 9, *DC Electrical Specification*s, to which the Spec was moved. • Spec 26. Changed -40 to T_L in the Min. column. • Spec 28 “Maximum Solder Temperature”: Added two lines: Lead free (PbFree) and Leaded (SnPb) with maximum values of 260 C and 245 C respectively. • Footnote 1, added: ‘any of’ between ‘beyond’ and ‘the listed maxima.’ • Deleted footnote 2: ‘Absolute maximum voltages are currently maximum burn-in voltages. Absolute maximum specifications for device stress have not yet been determined.’Spec 26 “Maximum Operating Temperature Range”: replaced -40 C with. • Footnote 6 (now footnote 5): Changed to the following sentence to the end, “Internal structures hold the input voltage greater than -1.0 V if the injection current limit of 2 mA is met. Keep the negative DC voltage greater than -0.6 V on eTPU[15] and on SINB during the internal power-on reset (POR) state.”
Table 3 MPC5567 Thermal Characteristics: Moved the Unit column to the far right column in the table.	
Table 4 EMI Testing Specifications:	• Changed the maximum operating frequency to from 132 to f_{MAX}. • Footnote 2: Deleted ‘Refer to Table 1 for the maximum operating frequency.’

Table 35. Table and Figure Changes Between Rev. 0.0 and 1.0 (continued)

Location	Description of Changes
Table 5 ESD Characteristics: Added *(Electromagnetic Static Discharge)* in the table title.	

Table 6, VCR/POR Electrical Specifications:	• Added footnote 1 to specs 1, 2, and 3 that reads: On power up, assert $\overline{\text{RESET}}$ before V_{POR15}, V_{POR33}, and V_{POR5} negate (internal POR). $\overline{\text{RESET}}$ must remain asserted until the power supplies are within the operating conditions as specified in Table 9 *DC Electrical Specifications*. On power down, assert $\overline{\text{RESET}}$ before any power supplies fall outside the operating conditions and until the internal POR asserts.
	• Subscript all symbol names that appear after the first underscore character.
	• Removed 'Tj ' after '150 C' in the last line, second column: Characteristic.
	• Reformatted column layout.
	• Added footnote 1 to specs 1, 2, and 3 that reads: On power up, assert $\overline{\text{RESET}}$ before V_{POR15}, V_{POR33}, and V_{POR5} negate (internal POR). RESET must remain asserted until the power supplies are within the operating conditions as specified in Table 9 *DC Electrical Specifications*. On power down, assert $\overline{\text{RESET}}$ before any power supplies fall outside the operating conditions and until the internal POR asserts.
	• Added to Spec 2:
	3.3 V (V_{DDSYN}) POR negated (ramp down) Min 0.0 Max 0.30 V
	3.3 V (V_{DDSYN}) POR asserted (ramp up) Min 0.0 Max 0.30 V
	• Spec 3: Added new footnote 3 for both lines: 'It is possible to reach the current limit during ramp up--do not treat this event as a short circuit current.'
	• Spec 5: Changed old Footnote 1 (now footnote 3): 'User must be able to supply full operating current for the 1.5V supply when the 3.3V supply reaches this range." to 'Supply full operating current for the 1.5 V supply when the 3.3 V supply reaches this range."
	• Specs 7 and 10: added 'at Tj ' at the end of the first line in the second column: Characteristic.
	• Spec 10:
	  • Changed the minimum values to: –40 C = 40; 25 C = 45; 150 C = 55.
	  • Added old footnote 5 as new footnote 7.
	  • Added cross-reference to footnote 6: 'I_{VRCCTL} is measured at the following conditions: V_{DD} = 1.35 V, V_{RC33} = 3.1 V, V_{VRCCTL} = 2.2 V.' Changed '(@ V_{DD} = 1.35 V, $f_{sys} = f_{MAX}$)' to '(@ $f_{sys} = f_{MAX}$).
	  • Added a new footnote 8, 'Refer to Table 1 for the maximum operating frequency.'
	  • Rewrote old footnote 7(new footnote 10) to: Represents the worst-case external transistor BETA. It is measured on a per part basis and calculated as ($I_{DD} \div I_{VRCCTL}$).
	• Added new footnote 2 to both lines in Spec 3: " V_{IL_S} (Table 9, Spec 15) is guaranteed to scale with V_{DDEH6} down to V_{POR5}.
	• Rewrote footnote 7 to read: Represents the worst-case external transistor BETA. It is measured on a per-part basis and calculated as ($I_{DD} \div I_{VRCCTL}$).
	• Deleted old footnote 8: 'Preliminary value. Final specification pending characterization.'

Table 7 Power Sequence Pin Status for Fast Pads	• Changed title to *Pin Status for Fast Pads During the Power Sequence* • Changed preceding paragraph From: Although there are no power up/down sequencing requirements to prevent issues like latch-up, excessive current spikes, etc., the state of the I/O pins during power up/down varies depending on power. Prior to exiting POR, the pads are in a high impedance state (Hi-Z). To: There are no power up/down sequencing requirements to prevent issues such as latch-up, excessive current spikes, and so on. Therefore, the state of the I/O pins during power up/down varies depending on which supplies are powered. • Deleted the 'Comment' column. • Added to row 2, column 3, 'Low' • Added row 3:' V_{DDE}, Low, Low, Asserted, High' and row 5: V_{DDE}, V_{DD33}, V_{DD}, Asserted, Hi-Z. • Added a POR column after the V_{DD} column; all column entries are 'Asserted' except row 6: V_{DDE}, V_{DD33}, V_{DD}, negated, Functional.

Table 35. Table and Figure Changes Between Rev. 0.0 and 1.0 (continued)

Location	Description of Changes
Table 8 Power Sequence Pin Status for Medium/Slow Pads:	• Changed title to *Pin Status for Medium and Slow Pads During the Power Sequence* • Updated preceding paragraph. • Deleted the 'Comment' column. • Added a POR column after the VDD column; all column entries are 'Asserted' except row 6: V_{DDE}, V_{DD33}, V_{DD}, negated, Functional. • Added row 3:' V_{DDEH}, V_{DD}, Asserted, Hi-Z.'
Table 9 DC Electrical Specifications:	• Added ($T_A = T_L - T_H$) to the end of the table title. • Spelled out meaning of the slash '/' as 'and' as well as 'I/O' as 'input/output.' Sentence still very confusing. Deleted 'input/output' from the specs to improve clarity. • Spec 20, column 2, *Characteristics*,' Slow and medium output high voltage (I_{OH_S} = –2.0 mA):' Created a left-justified second line and moved 'I_{OH_S} = –2.0 mA' from the 1st line to the second line and deleted the parentheses. Created a left-justified third line that reads 'I_{OH_S} = –1.0 mA.' • Spec 20, column 4, *Min*: Added a blank line before and after '0.80 × V_{DDEH}' and put '0.85 × V_{DDEH}' on the last line. • Spec 22, column 2, '*Slow and medium output low voltage (I_{OL_S} = 2.0 mA)*:' Created a left-justified second line and moved 'I_{OL_S} = 2.0 mA.' from the 1st line to the second line and deleted the parentheses. Created a left-justified third line that reads 'I_{OL_S} = 1.0 mA.' • Spec 22, column 5, *Max*: Added a blank line before and after '0.20 × V_{DDEH}' and put '0.15 × V_{DDEH}' on the last line. • Spec 26: Changed 'AN[12]_MA[1]_SDO' to 'AN[13]_MA[1]_SDO'. • Spec 27a: Characteristics column, 1st line, changed 132 MHz to 135 MHz. • Spec 28: Changed 132 MHz to f_{MAX} MHz. • Spec 29: Deleted @ 132 MHz. • Spec 45: Changed the Min value from -40.0 to T_L and the Max value from 125 to T_H. • Corrected footnote 3 to read: If standby operation is not required, connect the V_{STBY} to ground. • Footnote 9: Changed from 'Preliminary. Final specification pending characterization.' to 'Figure 2 shows an illustration of the I_{DD_STBY} values interpolated for these temperature values.'
Figure 2 *I_{STBY} Worst-case Specifications:*	Added introductory paragraph and figure to show interpolated IDD_{STBY} values listed in Table 9.

Table 35. Table and Figure Changes Between Rev. 0.0 and 1.0 (continued)

Location	Description of Changes
Table 12 FMPLL Electrical Characteristics:	• Added ($T_A = T_L - T_H$) to the end of the second line in the table title. • Spec 1, footnote 1 in column 2: *'PLL reference frequency range*': Changed to read 'Nominal crystal and external reference values are worst-case not more than 1%. The device operates correctly if the frequency remains within ± 5% of the specification limit. This tolerance range allows for a slight frequency drift of the crystals over time. The designer must thoroughly understand the drift margin of the source clock.' • Spec 1, added two more lines to the *PLL reference frequency range*' to read as follows: crystal reference (20) fref_crystal 8 ≤ 20 crystal reference (40) fref_crystal > 20 40 external reference (20) fref_ext 8 ≤ 20 external reference (40) fref_ext > 20 40 • Spec 1, footnote 2 in column 1: Changed to: 'The 8–20 MHz crystal or external reference values have PLLCFG[2] pulled low' and applies to spec 1, column 2, crystal reference and external reference. • Specs 12 and 13: Grouped (2 x CI). • Spec 21, column 2: Changed $f_{ref_crystal}$ to f_{ref} in ICO frequency equation, and added the same equation but substituted f_{ref_ext} for f_{ref} for the external reference clock, giving: $f_{ico} = [f_{ref_crystal} \times (MFD + 4)] \div (PREDIV + 1)$ $f_{ico} = [f_{ref_ext} \times (MFD + 4)] \div (PREDIV + 1)$ • Spec 21, column 4, Max: Deleted old footnote 18 that reads: The ICO frequency can be higher than the maximum allowable system frequency. For this case, set the CMPLL synthesizer control register reduced frequency divider (FMPLL_SYNCR[RFD]) to divide-by-two (RFD = 0b001). Therefore, for a 40 MHz maximum device (system frequency), program the FMPLL to generate 80 MHz at the ICO output and then divide-by-two the RFD to provide the 40 MHz system clock.' • Spec 21: Changed column 5 from 'f_{SYS}' MHz' to: 'f_{MAX}'. • Spec 22: Changed column 4, *Max Value* from f_{MAX} to 20, and added footnote 17 to read, 'Maximum value for dual controller (1:1) mode is ($f_{MAX} \div 2$) and the predivider set to 1 (FMPLL_SYNCR[PREDIV] = 0b001).'
Table 13 eQADC Conversion Specifications: Added ($T_A = T_L - T_H$) to the table title.	
Table 14 Flash Program and Erase Specifications:	• Added ($T_A = T_L - T_H$) to the table title. • Specs 7, 8, 9, and 10 Changed values for the H7Fa Flash pre-program and erase times and used the previous values for Typical values. -- 48 KB: from 340 to 345 -- 64 KB: from 400 to 415 • Spec 8, 128KB block pre-program and erase time, Max column value from 15,000 to 7,500. • Moved footnote 1 from the table title to directly after the 'Typical' in the column 5 header. • Footnote 2: Changed from: 'Initial factory condition: ≤ 100 program/erase cycles, 25 °C, typical supply voltage, 80 MHz minimum system frequency.' To: 'Initial factory condition: ≤ 100 program/erase cycles, 25 °C, using a typical supply voltage measured at a minimum system frequency of 80 MHz.'
Table 15 Flash EEPROM Module Life:	• Replaced (Full Temperature Range) with ($T_A = T_L - T_H$) in the table title. • Spec 1b, Min. column value changed from 10,000 to 1,000.

Table 35. Table and Figure Changes Between Rev. 0.0 and 1.0 (continued)

Location	Description of Changes
Table 16 FLASH BIU Settings vs. Frequency of Operations:	• 'Added footnote 1 to the end of the table title, The footnote reads: 'Illegal combinations exist. Use entries from the same row in this table.' • Moved footnote 2:' For maximum flash performance, set to 0b11' to the 'DPFEN' column header. • Deleted the x-refs in the 'DPFEN' column for the rows. • Created a x-ref for footnote 2 and inserted in the 'IPFEN' column header. • Deleted the x-refs in the 'IPFEN' column for the rows. • Moved footnote 3:' For maximum flash performance, set to 0b110' to the 'PFLIM' column header. • Deleted the x-refs in the 'PFLIM' column for the rows. • Moved footnote 4:' For maximum flash performance, set to 0b1' to the 'BFEN' column header. • Deleted the x-refs in the 'BFEN' column for the rows. • Changed footnotes 1, 5, and 6 to become footnotes 5, 6, and 7 -- footnote 5 82 MHz parts allow for 80 MHz system clock + 2% frequency modulation (FM). -- footnote 6 102 MHz parts allow for 100 MHz system clock + 2% FM. -- footnote 7 135 MHz parts allow for 132 MHz system clock + 2% FM. • Footnote 9: added to the end of the 1st column for the 147 MHz row that reads: Preliminary setting. Final setting pending characterization.
Table 17 Pad AC Specifications and *Table 18 Derated Pad AC Specifications*: The changes are identical in the tables.	• Footnote 1, deleted 'F_{SYS} = 132 MHz.' • Footnote 2, changed from 'tested' to '(not tested).' • Footnote 3, changed from 'Out delay. . .' to 'The output delay. . .', • Changed from ' Add a maximum of one system clock to the output delay to get the output delay with respect to the system clock' to 'To calculate the output delay with respect to the system clock, add a maximum of one system clock to the output delay.' • Footnote 4: changed 'Delay' to 'The output delay.' • Footnote 5: deleted 'before qualification.' • Changed from 'This parameter is supplied for reference and is not guaranteed by design and not tested' to 'This parameter is supplied for reference and is guaranteed by design and tested.'
Table 19 Reset and Configuration Pin Timing: Footnote 1, deleted 'F_{SYS} = 132 MHz,' and 'V_{DD} = 1.35–1.65.'	
Table 20 JTAG Pin AC Electrical Characteristics:	• Footnote 1, deleted: ', and CL = 30 pF with DSC = 0b10, SRC = 0b11' • Footnote 1, changed 'functional' to 'Nexus.'
Table 21 Nexus Debug Port Timing.	Changed Spec 12, TCK Low to TDO Data Valid: Changed 'VDDE = 3.0 to 3.6 volts' maximum value in column 4 from 9 to 10. Now reads 'V_{DDE} = 3.0–3.6 V' with a max value of 10.

Table 35. Table and Figure Changes Between Rev. 0.0 and 1.0 (continued)

Location	Description of Changes
Table 22 Bus Operation Timing:	• External Bus Frequency in the table heading: Added footnote that reads: Speed is the nominal maximum frequency. Max speed is the maximum speed allowed including frequency modulation (FM). 82 MHz parts allow for 80 MHz system clock + 2% FM; 114 MHz parts allow for 112 MHz system clock + 2% FM, and 135 MHz parts allow for 132 MHz system clock + 2% FM. • Spec 1: Changed the values in Min. columns: 40 MHz from 25 to 24.4; 56 MHz from 17.9 to 17.5, and the 66 MHz from 15.2 to 14.9. • Specs 5 and 6: *CLKOUT positive edge to output signals invalid of high*: Corrected format to show the bus timing values for various frequencies with EBTS bit = 0 and EBTS bit = 1. • Specs 5, and 6: Deleted the BG, BR, and TSIZ[0:1] signals for arbitration. Added the following calibration signals: CAL_ADDR[10:30], CAL_CS[0, 2:3], CAL_DATA[0:15], CAL_OE, CAL_RD_WR, CAL_TS, CAL_WE/BE[0:1]. • Specs 7 and 8: Deleted the BG, BR, and TSIZ[0:1] signals for arbitration. Added the following calibration signals: CAL_ADDR[10:30], CAL_DATA[0:15], CAL_RD_WR, and CAL_TS. • Added a footnote each for the DATA[0:31], TEA, and WE/BE[0:3] signals in the table: Due to pin limitations, the DATA[16:31], TEA, and WE/BE[2:3] signals are not available on the 324 package.
Table 23 External Interrupt Timing:	• Footnote 1: Deleted ‘F_{SYS} = 132 MHz.’,‘V_{DD} = 1.35–1.65 V’, ‘V_{DD33} and V_{DDSYN} = 3.0–3.6 V.’ and ‘ and CL = 200 pF with SRC = 0b11.’ • Deleted second figure after table ‘External Interrupt Setup Timing.’
Table 24 eTPU Timing	• Footnote 1: Deleted ‘F_{SYS} = 132 MHz.’, ‘V_{DD} = 1.35–1.65 V’, ‘V_{DD33} and V_{DDSYN} = 3.0–3.6’ and ‘ and CL = 200 pF with SRC = 0b11.’ • Deleted second figure, ‘*eTPU Input/Output Timing*’ after this table. • Added Footnote 2: ‘This specification does not include the rise and fall times. When calculating the minimum eTPU pulse width, include the rise and fall times defined in the slew rate control fields (SRC) of the pad configuration registers (PCR).’
Table 25 eMIOS Timing:	• Deleted (MTS) from the heading, table, and footnotes. • Footnote 1: Deleted ‘F_{SYS} = 132 MHz’, ‘V_{DD} = 1.35–1.65 V’, ‘V_{DD33} and V_{DDSYN} = 3.0–3.6 V’ and ‘ and CL = 200 pF with SRC = 0b11.’ • Added Footnote 2: ‘This specification does not include the rise and fall times. When calculating the minimum eMIOS pulse width, include the rise and fall times defined in the slew rate control fields (SRC) of the pad configuration registers (PCR).’
Figure 17 Added *eMIOS Timing* figure.	
Table 26 DSPI Timing:	• Table Title: Added footnote that reads: Speed is the nominal maximum frequency. Max speed is the maximum speed allowed including frequency modulation (FM). 82 MHz parts allow for 80 MHz system clock + 2% FM; 114 MHz parts allow for 112 MHz system clock + 2% FM, and 135 MHz parts allow for 132 MHz system clock + 2% FM. • Spec1:*SCK Cycle Time*: changes to values: 80 MHz, min = 24.4, max 2.9; 112 MHz, min = 17.5, max = 2.1; 132 MHz, min = 14.8, max = 1.8. • Footnote 1: Added to beginning of footnote 1 ‘All DSPI timing specifications use the fastest slew rate (SRC = 0b11) on pad type M or MH. DSPI signals using pad types of S or SH have an additional delay based on the slew rate.’ Deleted ‘V_{DD} = 1.35–1.65 V’ and ‘V_{DD33} and V_{DDSYN} = 3.0–3.6 V.

Table 35. Table and Figure Changes Between Rev. 0.0 and 1.0 (continued)

Location	Description of Changes
Table 27 EQADC SSI Timing Characteristics:	• Deleted from table title '(Pads at 3.3 V or 5.0 V)' • Deleted 1st line in table 'CLOAD = 25 pF on all outputs. Pad drive strength set to maximum.' • Spec 1: FCK frequency -- removed. • Combined footnotes 1 and 2, and moved the new footnote to Spec 2. Moved old footnote 3 that is now footnote 2 to Spec 2. • Footnote 1, deleted 'V_{DD} = 1.35–1.65 V' and 'V_{DD33} and V_{DDSYN} = 3.0–3.6V.' Changed 'CL = 50 pF' to 'CL = 25 pF.' • Footnote 2: added 'cycle' after 'duty' to read: FCK duty cycle is not 50% when . . . .
Figure 32 MPC5567 324 Package: Deleted the version number and date; changed ball label T21 from V_{RCVSS} to PLLCFG2.	
Figure 36 and *Figure 36MPC5567 416 Package*: Deleted the version number and date.	

THIS PAGE IS INTENTIONALLY BLANK

How to Reach Us:

Home Page:
www.freescale.com

Web Support:
http://www.freescale.com/support

USA/Europe or Locations Not Listed:
Freescale Semiconductor, Inc.
Technical Information Center, EL516
2100 East Elliot Road
Tempe, Arizona 85284
+1-800-521-6274 or +1-480-768-2130
www.freescale.com/support

Europe, Middle East, and Africa:
Freescale Halbleiter Deutschland GmbH
Technical Information Center
Schatzbogen 7
81829 Muenchen, Germany
+44 1296 380 456 (English)
+46 8 52200080 (English)
+49 89 92103 559 (German)
+33 1 69 35 48 48 (French)
www.freescale.com/support

Japan:
Freescale Semiconductor Japan Ltd.
Headquarters
ARCO Tower 15F
1-8-1, Shimo-Meguro, Meguro-ku,
Tokyo 153-0064
Japan
0120 191014 or +81 3 5437 9125
support.japan@freescale.com

Asia/Pacific:
Freescale Semiconductor China Ltd.
Exchange Building 23F
No. 118 Jianguo Road
Chaoyang District
Beijing 100022
China
+86 10 5879 8000
support.asia@freescale.com

For Literature Requests Only:
Freescale Semiconductor Literature Distribution Center
1-800-441-2447 or 303-675-2140
Fax: 303-675-2150
LDCForFreescaleSemiconductor@hibbertgroup.com

Document Number: MPC5567
Rev. 2
12/2012

Information in this document is provided solely to enable system and software implementers to use Freescale Semiconductor products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits or integrated circuits based on the information in this document.

Freescale Semiconductor reserves the right to make changes without further notice to any products herein. Freescale Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Freescale Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. “Typical” parameters that may be provided in Freescale Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including “Typicals”, must be validated for each customer application by customer’s technical experts. Freescale Semiconductor does not convey any license under its patent rights nor the rights of others. Freescale Semiconductor products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Freescale Semiconductor product could create a situation where personal injury or death may occur. Should Buyer purchase or use Freescale Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold Freescale Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Freescale Semiconductor was negligent regarding the design or manufacture of the part.

Freescale™ and the Freescale logo are trademarks of Freescale Semiconductor, Inc. All other product or service names are the property of their respective owners.

© Freescale Semiconductor, Inc. 2007,2012. All rights reserved.

RoHS-compliant and/or Pb-free versions of Freescale products have the functionality and electrical characteristics as their non-RoHS-compliant and/or non-Pb-free counterparts. For further information, see http://www.freescale.com or contact your Freescale sales representative.

For information on Freescale’s Environmental Products program, go to http://www.freescale.com/epp.

BUILT ON Power™

freescale™

Общество с ограниченной ответственностью «МосЧип» ИНН 7719860671 / КПП 771901001
Адрес: 105318, г.Москва, ул.Щербаковская д.3, офис 1107

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

http://moschip.ru/get-element

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

105318, г.Москва, ул.Щербаковская д.3, офис 1107, 1118, ДЦ «Щербаковский»

Телефон: +7 495 668-12-70 (многоканальный)

Факс: +7 495 668-12-70 (доб.304)

E-mail: info@moschip.ru

Skype отдела продаж:
moschip.ru
moschip.ru_4
moschip.ru_6
moschip.ru_9